

iC-HTG POWER CW LASER DIODE DRIVER

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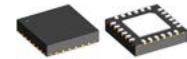
FEATURES

- ◆ CW operation with external driver transistor
- ◆ 3 to 24 V power supply
- ◆ Analog modulation frequency of up to 50 kHz
- ◆ Internal programmable logarithmic monitor resistor
- ◆ Operating point setup with a logarithmic resolution of 10 bits
- ◆ Current or power control mode (ACC/APC) configurable
- ◆ A/D converters for analog signals monitoring
- ◆ Serial programming interface (SPI or I²C compliant)
- ◆ Configuration RAM content integrity monitoring
- ◆ Optimized for both N-type and P-type laser diodes
- ◆ Low drop linear regulator for 3.3 V
- ◆ Low current standby mode
- ◆ Temperature monitor
- ◆ Temperature range of -40 to 85 °C

APPLICATIONS

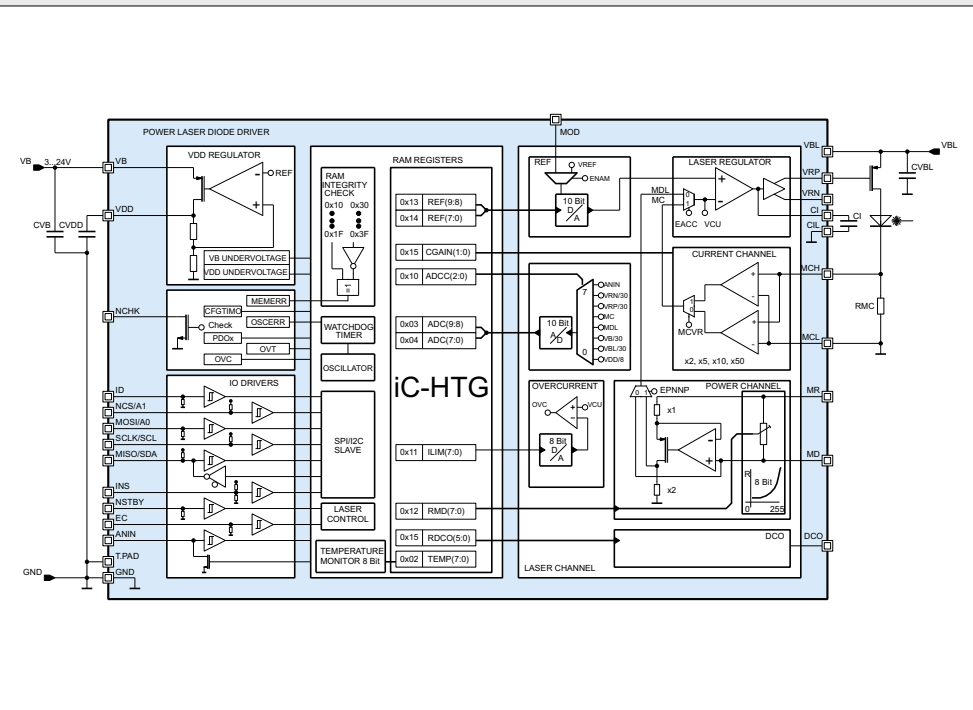
- ◆ Commercial LED/Laser diode modules
- ◆ Safety related CW laser diode drivers
- ◆ Structured-light 3D illumination
- ◆ Laser diode stack control
- ◆ Optical amplification
- ◆ Optical pumping

PACKAGES



QFN24 4 mm x 4 mm

BLOCK DIAGRAM



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iC-HTG

POWER CW LASER DIODE DRIVER

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DESCRIPTION

The CW power laser diode driver iC-HTG can operate a laser diode or LED with an external power transistor and features automatic current (ACC) and power (APC) control. All parameters, including the internal reference voltages, are set via serial communication (I²C or SPI). A 10-bit D/A converter with logarithmic or linear characteristic is used to set the operating point. This allows an operating point resolution better than 1%. In APC mode, the monitor diode photocurrent is used to track the optically emitted power of the laser diode. The voltage across the resistor through which the photocurrent flows is used for feedback in the control loop. An internal 8-bit programmable logarithmic monitor resistor (PLR) or an external monitor resistor can be selected to close the control loop. The PLR ranges from 100 Ω to 407 kΩ with a step width of less than 5%. In ACC mode, the laser diode current can be measured by means of a low impedance shunt resistor. The output power can be analog modulated with a frequency of up to 50 kHz. iC-HTG allows the laser channel to be disabled when an overcurrent threshold has been exceeded. The overcurrent threshold is programmable using an 8-bit linear D/A converter. The temperature monitor measures the internal chip temperature. iC-HTG disables the laser channel when

overtemperature is detected. A number of voltages can be measured with a 10-bit A/D converter:

- V(VB)
- V(VBL)
- V(VDD)
- V(ANIN)
- V(MC)
- V(MDL)
- V(VRP)
- V(VRN)

The current output pin DCO can be used to adjust an external DC/DC converter. Controlling the DC/DC output voltage may optimize the power dissipation of the whole system to extend battery life, for example. In standby mode iC-HTG has a very low current consumption (typ. < 10 μA) while retaining its configuration. The device features for **safe operation** are:

- Configuration RAM content integrity monitored
- Tri-state configuration pins
- Write protection in operating mode
- Safe power-up state

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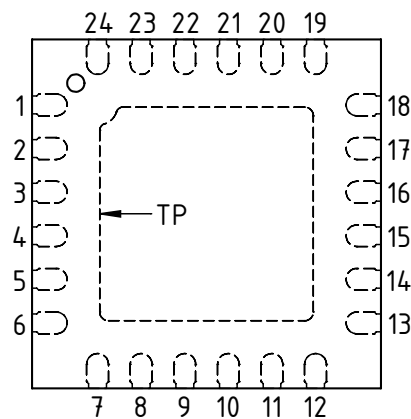
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PACKAGING INFORMATION QFN24 4 mm x 4 mm to JEDEC

PIN CONFIGURATION QFN24 4 mm x 4 mm (topview)



PIN FUNCTIONS

| No. | Name | Function |
|-----|----------|--|
| 1 | NCHK | Check output, active low |
| 2 | NSTBY | Standby input, active low |
| 3 | NCS/A1 | Chip Select, active low / I ² C Address bit 1 |
| 4 | ID | I ² C address bit 2 |
| 5 | EC | Enable Channel input |
| 6 | MOSI/A0 | SPI Master Out Slave In / I ² C Address Bit 0 |
| 7 | SCLK/SCL | SPI Clock / I ² C Clock |
| 8 | MISO/SDA | SPI Master In Slave OUT / I ² C Data |
| 9 | ANIN | Analog input for ADC |
| 10 | MCH | Current monitor high side |
| 11 | MCL | Current monitor low side |
| 12 | MOD | Analog modulation |
| 13 | CI | Integration Capacitor high side |
| 14 | CIL | Integration Capacitor low side |
| 15 | VRN | N transistor control |
| 16 | VRP | P transistor control |
| 17 | VBL | Channel supply |
| 18 | MD | Monitor diode |
| 19 | MR | Monitor resistor |
| 20 | GND | Ground |
| 21 | DCO | DC/DC converter trimmer |
| 22 | INS | I ² C or SPI selection input |
| 23 | VDD | 3.3V output supply |
| 24 | VB | Power supply |

BP(TP) Backside Paddle (GND) ¹⁾

IC top marking: <P-CODE> = product code, <A-CODE> = assembly code (subject to changes).

1) Connecting the backside paddle is recommended by a single link to GND. A current flow across the paddle is not permissible.

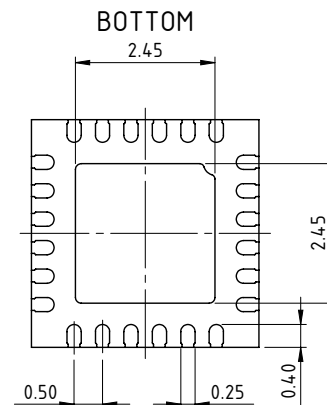
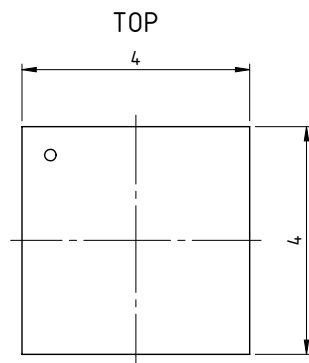
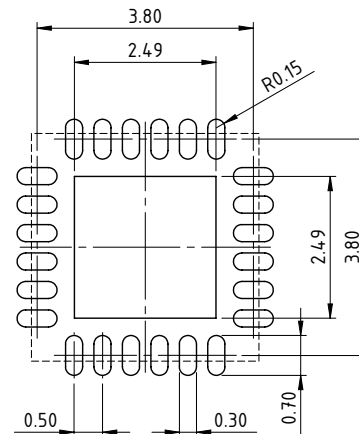
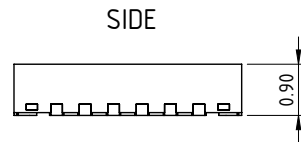
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PACKAGE DIMENSIONS QFN24-4x4

All dimensions given in mm.
This package falls within JEDEC MO-220-VHHD-1.

RECOMMENDED PCB-FOOTPRINT



dra_gfn24-1_pack_1_10:1

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ABSOLUTE MAXIMUM RATINGS

These ratings do not imply permissible operating conditions; functional operation is not guaranteed. Exceeding these ratings may damage the device.

| Item No. | Symbol | Parameter | Conditions | | | Unit |
|----------|--------|--|--|------|----------|----------|
| | | | | Min. | Max. | |
| G001 | VB | Voltage at VB, VBL | | -0.3 | 30 | V |
| G002 | I(VB) | Current in VB, VBL | | -20 | 50 | mA |
| G003 | VDD | Voltage at VDD | | -0.3 | 5.5 | V |
| G004 | I(VDD) | Current in VDD | | -20 | 1 | mA |
| G005 | V() | Voltage at DCO, ANIN, SCLK/SCL, MISO/SDA, MOSI/A0, NCS/A1, DCO, INS, NCHK, CI, MOD, EC | | -0.3 | 5.5 | V |
| G006 | V() | Voltage at VRP, VRN, MCH, MCL, NSTBY | | | 30 | V |
| G007 | I() | Current in DCO, ANIN, SCLK/SCL, MISO/SDA, MOSI/A0, NCS/A1, DCO, INS, NCHK, CI, VRP, VRN, MCH, MCL, NSTBY, EC | | -20 | 20 | mA |
| G008 | V() | Voltage at CIL | | -0.3 | 0.5 | V |
| G009 | I(CIL) | Current in CIL | DC current | -900 | 1 | mA |
| G010 | Vd() | ESD Susceptibility at all pins | HBM 100 pF discharged through 1.5kΩ CDM (JEDEC Standard No. 22-C101F) | | 2 0.5 | kV kV |
| G011 | Tj | Operating Junction Temperature | | -40 | 85 | °C |
| G012 | Ts | Storage Temperature Range | | -40 | 150 | °C |

THERMAL DATA

Operating Conditions: VB = 3 ... 24 V (referenced to GND)

| Item No. | Symbol | Parameter | Conditions | | | | Unit |
|----------|--------|-------------------------------------|----------------|------|------|------|------|
| | | | | Min. | Typ. | Max. | |
| T01 | Ta | Operating Ambient Temperature Range | | -40 | | 85 | °C |
| T02 | Rthja | Thermal Resistance Chip/Ambient | Mounted on PCB | | 25 | | K/W |
| T03 | RthjTP | Thermal Resistance Chip/Thermal Pad | | | 4 | | K/W |

All voltages are referenced to ground unless otherwise stated.
All currents flowing into the device pins are positive; all currents flowing out of the device pins are negative.

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ELECTRICAL CHARACTERISTICS

Operating Conditions: VB = VBL = 3 ... 24 V (relative to GND), Tj = -40 ... 125 °C unless otherwise stated

| Item No. | Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|--|------------|---|---|------------------------|------|---------------------------|----------------------|
| General | | | | | | | |
| Functionality and parameters beyond the operating conditions (with reference to independent voltage supplies, for instance) are to be verified within the individual application using FMEA methods. | | | | | | | |
| 001 | VB | Permissible Supply Voltage | Relative to GND | 3 | | 24 | V |
| 002 | I(VB) | Standby Current at VB | V(NSTBY) ≤ 0.4 V; VB = 3... 11 V VB = 11... 24 V | | | 10 30 | μA μA |
| 003 | I(VBL) | Standby Current at VBL | V(NSTBY) ≤ 0.4 V; VBL = 3... 11 V VBL = 11... 24 V | | | 10 25 | μA μA |
| 004 | I(VB) | Supply Current at VB | No load, EC, NSTBY = hi | | | 5 | mA |
| 005 | I(VBL) | Supply Current at VBL | No load, EC, NSTBY = hi | | | 25 | mA |
| 006 | V(VB)on | Turn-off threshold at VBL | Increasing VBL | 1 | | 2.9 | V |
| 007 | V(VB)off | Turn-off threshold at VB, VBL | Decreasing VB, VBL | 0.8 | | 2.6 | V |
| 008 | V(VBL)Hys | Power-on hysteresis at VBL | | 20 | | 500 | mV |
| 009 | V(VDD)on | Turn-on threshold | Increasing VDD | 1.3 | | 2.4 | V |
| 010 | V(VDD)off | Turn-off threshold | Decreasing VDD | 1.2 | | 2.3 | V |
| 011 | V(VDD)Hys | Power-on hysteresis | | 20 | | 250 | mV |
| 012 | V(VB)INITR | RAM memory reset during Standby | NSTBY = lo | | 1.4* | | V |
| 013 | RCIL() | Resistor between GND and CIL | | | | 20 | Ω |
| 014 | Vc()Io | Clamp Voltage Io at VB, VBL, VDD, NCHK, NCS/A1, MISO/SDA, MOSI/A0, SCLK/SCL, INS, NSTBY, EC, DCO, CI, MD, MR, MCH, MCL, VRP, VRN, MOD | I() = -10 mA | -1.6 | | -0.3 | V |
| Transistor Driver VRx, Cx, MCx, MR, MD | | | | | | | |
| 101 | C(CI) | Required capacitor at CI | CW Analog Modulation | 1000 | 80 | | pF pF |
| 102 | I(CI) | Charge Current at CI | V(CI) = 0 V, CI regulated | -30 | | -5 | μA |
| 103 | V(MCx) | Permissible Voltage at MCH, MCL | EC = hi, NSTBY = hi; MCVR = lo MCVR = hi | 0 VBL - 5 | | 0.8 VBL | V V |
| 104 | V(MR,MD) | Permissible Voltage at MR, MD | EC = hi, NSTBY = hi; EPNNP = lo EPNNP = hi | 0 VDD - 1.2 | | 1.2 VDD | V V |
| 105 | I(VRP)hi | VRP Current High | VBL = 3... 8 V, VRP = 0 V VBL = 8... 24 V, VRP = VBL - 8 V | | | -0.25 -1 | mA mA |
| 106 | I(VRP)lo | VRP Current low | VBL = 3... 5 V, VRP = VBL VBL = 5... 24 V, VRP = 8 V | 10 40 | | | mA mA |
| 107 | I(VRN)Hi | VRN current High | VRNHR = 1, VBL = 3... 8 V, VRN = 0 V VRNHR = 1, VBL = 8... 24 V, VRN = 0 V VRNHR = 0, VBL = 4.5... 8 V, VRN = 0 V VRNHR = 0, VBL = 8... 24 V, VRN = 10 V | | | -0.25 -1 -10 -40 | mA mA mA mA |
| 108 | I(VRN)lo | VRN current Low | VRNHR = 1, VBL = 3... 8 V, VRN = VBL VRNHR = 1, VBL = 8... 24 V, VRN = 5 V VRNHR = 0, VBL = 3... 8 V, VRN = VBL VRNHR = 0, VBL = 8... 24 V, VRN = 8 V | 10 30 10 40 | | | mA mA mA mA |
| 109 | V(VRP) | Voltage output range | No load, channel enabled; VBL = 3V VBL = 9V VBL = 15V VBL = 24V | 1.9 3 3.5 4.5 | | 3 9 15 24 | V V V V |

* Projected value by sample characterization

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ELECTRICAL CHARACTERISTICS

Operating Conditions: VB = VBL = 3 ... 24 V (relative to GND), Tj = -40 ... 125 °C unless otherwise stated

| Item No. | Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|---|------------|--|---|--------------|--------------|--------------|----------|
| 110 | V(VRN) | Voltage output range | No load, channel enabled; | | | | |
| | | | VRNHR = lo, VBL = 3 V | 0 | | 1 | V |
| | | | VRNHR = lo, VBL = 9 V | 0 | | 6.5 | V |
| | | | VRNHR = lo, VBL = 15 V | 0 | | 12 | V |
| | | | VRNHR = lo, VBL = 24 V | 0 | | 19 | V |
| | | | VRNHR = hi, VBL = 3 V | 1.8 | | 3 | V |
| | | | VRNHR = hi, VBL = 9 V | 2.3 | | 9 | V |
| | | | VRNHR = hi, VBL = 15 V | 3.1 | | 15 | V |
| | | VRNHR = hi, VBL = 24 V | 4 | | 24 | V | |
| 111 | Ten | Time to laser enabled | NSTBY lo → hi, no load at VDD, V(VDD) 0 to 90%, CVDD = 1 μF | | 1.3 | | ms |
| Programmable Resistor | | | | | | | |
| 201 | Rmda | Resistor at MD and MR pin | RMD(7:0) = 0xFF, DISP = 0 RMD(7:0) = 0x00, DISP = 0 | 350 0.154 | 500 0.220 | 650 0.286 | kΩ kΩ |
| 202 | Tk | Temperature coefficient | | | -500 | | ppm/K |
| 203 | ΔR | Resistor increment | $\Delta R = \frac{R(n+1) - R(n)}{R(n)}$ | 1 | 3.3 | 7 | % |
| 204 | Ileak(MDA) | MD, MR leakage current | DISP = 1 | -2 | | 2 | μA |
| D/A Converter | | | | | | | |
| 301 | RES(DAC) | D/A Converter Resolution | | | | 10 | bit |
| 302 | ΔV | Voltage increments | LINLOG = 0, $\Delta V = \frac{V(n+1) - V(n)}{V(n)}$ | 0.05 | 0.235 | 1 | % |
| 303 | ΔV | Voltage increments | LINLOG = 1 | | 1 | | mV |
| 304 | V(DAC) | D/A Converter | LINLOG = 0/1; | | | | |
| | | | REF(9:0) = 0x000 lowest value REF(9:0) = 0x3FF highest value | 0.09 1.00 | 0.10 1.10 | 0.12 1.25 | V V |
| 305 | V(REF) | D/A Converter | V(MOD) = 1.1 V, analog modulation enabled, LINLOG = 0/1; | | | | |
| | | | REF(9:0) = 0x000 lowest value REF(9:0) = 0x3FF highest value | 0.09 1.00 | 0.10 1.10 | 0.12 1.25 | V V |
| 306 | G() | Gain Factor | ACC mode; | | | | |
| | | | CGAIN(1:0) = 00 | 1.5 | 2 | 2.5 | |
| | | | CGAIN(1:0) = 01 | 3 | 5 | 7.9 | |
| | | | CGAIN(1:0) = 10 | 6.1 | 10 | 15.9 | |
| | | | CGAIN(1:0) = 11 | 35 | 50 | 70 | |
| Check Output NCHK | | | | | | | |
| 401 | Vs()lo | Saturation Voltage lo at NCHK | I(NCHK) = 1.0 mA | | | 0.4 | V |
| 402 | Isc()lo | Short Circuit Current lo at NCHK | V(NCHK) = 0.4 ... 3.3 V | 3 | | 33 | mA |
| 403 | Iik() | Leakage Current at NCHK | NCHK = 1, V(NCHK) = 0 ... 5.5 V | -10 | | 10 | μA |
| Series Regulator Output VDD | | | | | | | |
| 501 | V(VDD) | Regulated output voltage | I(VDD) = -10 ... 0 mA, NSTBY = hi | 3 | | 3.5 | V |
| 502 | V(VB,VDD) | Voltage Drop between VB and VDD | VB = 3 V, I(VDD) = -10 ... 0 mA, NSTBY = hi | | 300 | 690 | mV |
| 503 | C(VDD) | Capacitor at VDD | Ri(C) < 1 Ω | 1 | | 3.3 | μF |
| 504 | Tvdd | Settling time VDD | NSTBY lo → hi, no load at VDD, V(VDD) 0 to 90%, CVDD = 1 μF | | | 1 | ms |
| 505 | Isc(VDD) | Short circuit current at VDD | VDD Connected to GND | -125 | | | mA |
| Digital inputs/output NCS/A1, MISO/SDA, MOSI/A0, SCLK/SCL, ID, NSTBY, EC, ANIN | | | | | | | |
| 601 | Vt(jhi) | Input Threshold Voltage hi at NCS/A1, MISO/SDA, MOSI/A0, SCLK/SCL, ID, NSTBY, EC, ANIN | MISO/SDA as input with INS = hi | | | 2 | V |
| 602 | Vt(jlo) | Input Threshold Voltage lo at NCS/A1, MISO/SDA, MOSI/A0, SCLK/SCL, ID, NSTBY, ANIN, EC, ANIN | MISO/SDA as input with INS = hi | 0.8 | | | V |

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ELECTRICAL CHARACTERISTICS

Operating Conditions: $V_B = V_{BL} = 3 \dots 24$ V (relative to GND), $T_J = -40 \dots 125$ °C unless otherwise stated

| Item No. | Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|----------------------------|----------|--|--|----------|-----------|-----------|----------------|
| 603 | Vt(hys) | Hysteresis at NCS/A1, MISO/SDA, MOSI/A0, SCLK/SCL, ID, NSTBY, ANIN, EC | $V_t(\text{hys}) = V_t(\text{hi}) - V_t(\text{lo})$ | 50 | | | mV |
| 604 | Ipd() | Pull-Down Current at MOSI/A0, EC | $V() = 0.4$ V ... VDD | 1 | | 50 | µA |
| 605 | Ipd() | Dynamic Pull-Down Current at NSTBY | $V() = 0.4$ V ... $V_t(\text{lo})$ $V() = V_t(\text{hi}) \dots V_B$ | 1 0.5 | | 50 15 | µA µA |
| 606 | Rpu() | Pull-Up Resistor at NCS/A1, SCLK/SCL | | 80 | 150 | 260 | kΩ |
| 607 | Rpu() | Pull-Up Resistor at MISO/SDA | INS = lo INS = hi | 8 53 | 20 100 | 50 174 | kΩ kΩ |
| 608 | Er() | Safe enable threshold voltage at INS | Rising Falling | 52 30 | 54 32 | 56 34 | % VDD % VDD |
| 609 | Voc() | Open Circuit Voltage at INS | | 40 | 41 | 45 | % VDD |
| 610 | Ri() | Internal Resistance at INS | | 170 | 250 | 360 | kΩ |
| 611 | Isc(lo) | Short Circuit current lo at MISO/SDA | INS = lo, $V(\text{MISO/SDA}) = 5.5$ V | -40 | | -4 | mA |
| 612 | Vs(lo) | Saturation Voltage lo at MISO/SDA | INS = lo, $I(\text{MISO/SDA}) = 2$ mA | | | 0.4 | V |
| 613 | Isc(lo) | Short Circuit current lo at ANIN | ANIN as output, $V(\text{ANIN}) = 5.5$ V | -40 | | -4 | mA |
| 614 | Vs(lo) | Saturation Voltage lo at ANIN | ANIN as output, $I(\text{ANIN}) = 2$ mA | | | 0.4 | V |
| A/D Converter | | | | | | | |
| 701 | Ton | Converter initialization time | ENAD changes from 0 to 1 | | | 500 | µs |
| 702 | Tconv | Conversion time | ENAD 0→1 to DRDY 0→1 | | | 140 | µs |
| 703 | RES(ADC) | A/D Converter Resolution | | | | 10 | bit |
| 704 | RAC | Relative Accuracy | | -1 | | +1 | LSB |
| 705 | VZS() | Zero Scale Voltage | ADC(9:0) = 0x000 | | 0 | | V |
| 706 | VFS() | Full Scale Voltage | ADC(9:0) = 0x3FF | 1.0 | 1.1 | 1.2 | V |
| 707 | VDDM() | VDD Measurement | $V_{DD} = 3.3$ V, ADCC(2:0) = 000, ENADCDIV = 1 | 334 | 368 | 402 | LSB |
| 708 | VBML() | VBL Measurement | $V_{BL} = 24$ V, ADCC(2:0) = 001, ENADCDIV = 1 | 654 | 720 | 786 | LSB |
| 709 | VBM() | VB Measurement | $V_B = 24$ V, ADCC(2:0) = 010, ENADCDIV = 1 | 654 | 720 | 786 | LSB |
| 710 | MDLM() | MDL Measurement | $ V(\text{MD}) - V(\text{MR}) = 0.5$ V, ADCC(2:0) = 011 | 413 | 455 | 497 | LSB |
| 711 | MCM() | $V(\text{MCH}) - V(\text{MCL})$ Measurement | $V(\text{MCH}) < 0.8$ V, $V(\text{MCH}) - V(\text{MCL}) = 0.25$ V, CGAIN(1:0) = 000, ADCC(2:0) = 100 | 320 | 480 | 640 | LSB |
| 712 | VRNM() | VRN Measurement | $V_{RN} = V_{BL} = V_B = 12$ V, ADCC(2:0) = 101, ENADCDIV = 1 | 330 | 365 | 402 | LSB |
| 713 | VRPM() | VRP Measurement | $V_{RP} = 24$ V, ADCC(2:0) = 110, ENADCDIV = 1 | 658 | 724 | 790 | LSB |
| 714 | ANINM() | ANIN Measurement | ANIN = 0.5 V, ADCC(2:0) = 111 | 409 | 451 | 493 | LSB |
| Overtemperature | | | | | | | |
| B01 | Toff | Overtemperature Shutdown | Rising temperature | 130 | | 170 | °C |
| B02 | Ton | Overtemperature Release | Falling temperature | 125 | | 165 | °C |
| B03 | Thys | Hysteresis | Toff – Ton | 3 | | | °C |
| Temperature Monitor | | | | | | | |
| C01 | Trange | Temperature Measurement Range | | -40 | | 125 | °C |
| C02 | Tresol | Temperature Measurement Resolution | | | 1 | | °C |
| C03 | TEMP | Temperature Value Ranges | $T_J = 125$ °C $T_J = -40$ °C | 160 0 | | 190 15 | LSB LSB |
| DCO Output | | | | | | | |
| D01 | Isc(hi) | DCO Output Current | $V(\text{VDD}) = 3 \dots 3.5$ V, $V(\text{DCO}) < 1.4$ V, RDCO = 0x3F | -175 | -130 | -85 | µA |

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ELECTRICAL CHARACTERISTICS

Operating Conditions: $V_B = V_{BL} = 3 \dots 24 \text{ V}$ (relative to GND), $T_j = -40 \dots 125 \text{ }^\circ\text{C}$ unless otherwise stated

| Item No. | Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-------------------|------------------------|----------------------------|---|------|-------|------|--------|
| D02 | I _{leak} | Leakage Current at DCO | RDCO = 0x00 or NSTBY = lo, V(DCO) = 0 ... V(VDD) | -1 | | 1 | μA |
| D03 | I(DCO)LSB | I(DCO) Resolution | V(DCO) < 1.4 V | 1.3 | 2 | 2.7 | μA |
| Oscillator | | | | | | | |
| E01 | F _(osc) | Oscillator Frequency | NSTBY = hi | 100 | 200 | 400 | kHz |
| E02 | T _(CFGTIMO) | Configuration Mode Timeout | MODE(1:0) = 10, count of oscillator pulses | | 16400 | | Pulses |
| E03 | tWDT | Watchdog Timeout | NSTBY = hi | 20 | | 120 | μs |

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OPERATING REQUIREMENTS: SPI and I²C Interface

Operating Conditions: $V_B = 3 \dots 24 \text{ V}$, $T_j = -40 \dots 85 \text{ }^\circ\text{C}$

| Item No. | Symbol | Parameter | Conditions | Timing | | Unit |
|--|---------|---|--|-----------|------|----------|
| | | | | Min. | Max. | |
| SPI / I²C Interface Timing | | | | | | |
| I001 | tsCCL | Setup Time: NCS/A1 hi \rightarrow lo before SCLK lo \rightarrow hi | INS = lo | 20 | | ns |
| I002 | tsDCL | Setup Time: MOSI/A0 stable before SCLK/SCL lo \rightarrow hi | INS = lo | 20 | | ns |
| I003 | thDCL | Hold Time: MOSI/A0 stable after SCLK/SCL lo \rightarrow hi | INS = lo | 5 | | ns |
| I004 | tCLH | Signal Duration SCLK/SCL hi | INS = lo INS = hi | 5 1250 | | ns ns |
| I005 | tCLL | Signal Duration SCLK/SCL lo | INS = lo INS = hi | 5 1250 | | ns ns |
| I006 | thCLC | Hold Time: NCS/A1 lo after SCLK/SCL hi \rightarrow lo | INS = lo | 5 | | ns |
| I007 | tCSH | Signal Duration NCS/A1 hi | INS = lo | 20 | | ns |
| I008 | tpCLD | Propagation Delay: MISO/SDA stable after SCLK/SCL hi \rightarrow lo | $V(V_{DD}) > 3 \text{ V}$, $C_{load} = 10 \text{ pF}$, no external pull-up | 0 | 30 | ns |
| I009 | f(SCLK) | SPI clock frequency | | | 10 | MHz |
| I010 | f(SCL) | I ² C clock frequency | | | 400 | kHz |

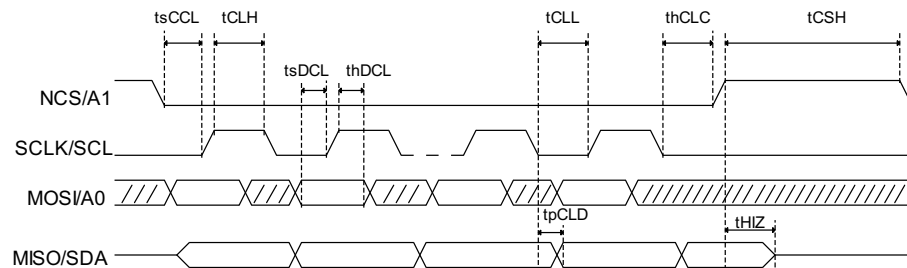


Figure 1: SPI / I²C interface timing

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STANDBY

iC-HTG enters standby mode by setting pin NSTBY low. In standby mode with no current drained from pin VDD, the current consumption at VB is reduced to e.g. 10 μ A max. (cf. *Electrical Characteristics No. 002*) and the chip retains its RAM configuration.

In order to exit standby mode, pin NSTBY must be set to hi, e.g. to the supply voltage at VB. When connecting it to VB, a resistor of at least 1 k Ω in series is required

for protection. As VDD is switched off in standby mode, it cannot be used to exit standby.

After wake-up (pin NSTBY's rising edge), the internal regulated supply voltage at VDD returns to its nominal value at a rate depending on the capacitor connected to pin VDD (cf. *Electrical Characteristics No. 504*).

More information about the start-up procedure on page 29.

OPERATION MODE

iC-HTG has two main modes: configuration mode and operation mode. The mode is set in register MODE(1:0).

| MODE(1:0) | | Addr. 0x1C; bit 1:0 | R/W 01 |
|-----------|---|---------------------|--------|
| Code | Function | | |
| 00 | Not allowed, signaled as memory error | | |
| 01 | Chip set in operation mode (apply configuration, latch transparent) | | |
| 10 | Chip set in configuration mode (hold previous configuration) | | |
| 11 | Not allowed, signaled as memory error | | |

Table 5: Select configuration or operation mode

The internal parameters of iC-HTG are set in configuration mode via I²C or SPI using a microcontroller. In this mode the configuration memory can be written and read back without changing the current configuration state of iC-HTG. Once the configuration is verified and accepted as valid, iC-HTG can be switched to operation mode and the new configuration will be activated. More information about configuration and operation modes and the serial communication interface on pages 27 and 18.

In operation mode, the driver is enabled by setting pin EC to hi. Setting register bit DISC to '1' disables the driver. If either pin EC is low or register bit DISC is high, the laser is disabled.

| DISC | | Addr. 0x10; bit 3 | R/W 1 |
|------|-------------------------------------|-------------------|-------|
| Code | Function | | |
| 0 | Channel can be enabled by pin EC | | |
| 1 | Channel cannot be enabled by pin EC | | |

Table 6: Disable channel

The iC-HTG can be configured for two control modes: laser-light power-control (APC) and laser current control (ACC). The control mode is selected by setting the EACC register. More about control modes is on page 13.

| EACC | | Addr. 0x10; bit 0 | R/W 0 |
|------|--|-------------------|-------|
| Code | Function | | |
| 0 | APC mode enabled (laser power control) | | |
| 1 | ACC mode enabled (laser current control) | | |

Table 7: Select APC or ACC

Laser enabling and error handling

Setting register bit DISC to '0' enables the laser channel.

The input pin INS needs to be high or low. With an open floating INS pin a corresponding internal error signal is generated (INSOPEN).

Internal INSOPEN error signal and status errors shown in Figure 2 disable the laser channel. Every change in the STATUS0 or STATUS1 registers is signaled at pin NCHK, unless the error event is masked by the corresponding error mask bit.

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| Register | Address | Bits | Default | Description |
|----------|---------|------|---------|---|
| INITRAM | 0x00 | 0 | R/O | RAM initialized |
| PDOVDD | 0x00 | 1 | R/O | Power down event at VDD |
| MEMERR | 0x00 | 2 | R/O | RAM memory validation error |
| OVT | 0x00 | 3 | R/O | Overtemperature event |
| PDOVBL | 0x00 | 4 | R/O | Power down event at VBL |
| OVC | 0x00 | 5 | R/O | Overcurrent |
| OSCERR | 0x00 | 6 | R/O | Oscillator error (watchdog set) |
| CFGTIMO | 0x00 | 7 | R/O | Configuration mode timeout event |
| MAPC | 0x01 | 0 | R/O | Channel current state read back |
| MONC | 0x01 | 1 | R/O | Channel enabled at least once (latched) |
| EC | 0x01 | 2 | R/O | EC pin current state read back |
| NMCOK | 0x01 | 3 | R/O | Current feedback status |

Table 8: Status registers overview

In order to enable the channel, the error events must be acknowledged. Acknowledging an error is accomplished by reading the corresponding STATUS register. After a power-on, PDOVDD and INITRAM errors will be set, therefore it is required to read the registers STATUS0 and STATUS1 after each power-on.

Exiting standby mode does not reset the RAM, but does set the PDOVDD status bit. Therefore STATUS0 must be read once after each standby to re-enable the laser channel.

In case of an overcurrent (OVC) or an overtemperature (OVT) event, the laser channel is disabled.

A memory error event (MEMERR) or a configuration timeout error event (CFGTIMO) also disables the laser

channel. More information about the memory error is on page 27. The conditions to enable the laser channel are shown in Figure 2.

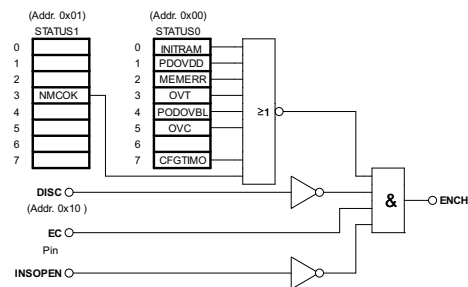


Figure 2: Laser control logic

CONTROL MODES AND LASER DIODE/LED TYPES

iC-HTG features no integrated driver transistor. External power transistors (P-channel or N-channel) can be driven, connecting the gate of the transistor to pins VRP or VRN. Another possibility is to control a DC/DC converter directly, providing the best power efficiency.

iC-HTG can be configured for two control modes: laser power control (APC) and laser current control (ACC). The control mode is selected by setting bit EACC.

| EACC | Addr. 0x10; bit 0 | R/W 0 |
|------|--|-------|
| Code | Function | |
| 0 | APC mode enabled (laser power control) | |
| 1 | ACC mode enabled (laser current control) | |

Table 9: Select APC or ACC

CI capacitor

For most applications a CI capacitor of at least 220 pF is recommended in order to ensure the stability of the control loop. The exact amount of capacitance needed depends on many factors such as PCB layout, output transistor, laser diode, and current range. The CI capacitor is used for APC and ACC. In APC configurations where the transistor gate is controlled by VRP, an additional capacitor (typ. 10 nF) from VRP to CI can further improve the control loop stability.

ACC mode

In ACC mode, the laser current is controlled. ACC mode is selected by setting bit EACC to '1'. In this mode, an external shunt resistor (RMC) is used to monitor the laser diode current. The voltage drop across this shunt resistor serves as feedback to the control

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loop. To feed the current voltage drop to the control loop, the shunt resistor must be connected to the pins MCH and MCL. The voltage drop $MCx = V(MCH) - V(MCL)$ needs to be positive. This voltage drop is internally amplified by a factor of 2, 5, 10 or 50. This factor can be selected using the register CGAIN(1:0). The resistor has to be chosen so that the value of the voltage drop multiplied by the amplification factor does not exceed the higher value of the reference generated with the 10-bit logarithmic D/A converter. This value is typically 1 V. More on this is on page 20.

| CGAIN(1:0) | | Addr. 0x15; bit 7:6 | R/W 00 |
|------------|--------------------------|---------------------|--------|
| Code | Function | | |
| 00 | Amplification set to x2 | | |
| 01 | Amplification set to x5 | | |
| 10 | Amplification set to x10 | | |
| 11 | Amplification set to x50 | | |

Table 10: MCx voltage drop amplification

Depending on the output configuration and the position of RMC in the current path, the voltage between pins MCH and MCL will be in between 0 and 5 V or in the range from $VBL - 5V$ to VBL . The MCx voltage range can be set with the register bit MCVR.

| MCVR | | Addr. 0x13; bit 2 | R/W 0 |
|------|--|-------------------|-------|
| Code | Function | | |
| 0 | MCx Voltage Range is 0 to 5V | | |
| 1 | MCx Voltage Range is $VBL - 5V$ to VBL | | |

Table 11: MCx voltage range

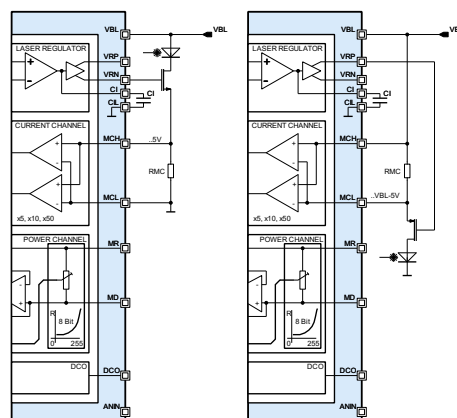


Figure 3: Operation in ACC mode with N-channel or P-channel output transistor. $EACC = 1$, $MCVR = 0$ and $MCVR = 1$

In ACC mode the register EPNNP is ignored.

Examples of connecting RMC using N-channel and P-channel transistors are shown in Figure 3.

By using the output transistor as a source follower like in Figure 3, the system shows increased stability and the CI capacitor can be smaller. This is recommended for analog modulation with pin MOD. There are many other configurations possible depending on laser type, transistor, and voltage range. More information on page 34.

ACC mode monitoring the optical power

In ACC mode, the optical power can be measured using a laser with an integrated photodiode (N-type or P-type). Connecting the photodiode to pin MD, a proportional voltage to the photocurrent can be measured with the 10-bit linear A/D converter. Two examples of ACC mode using a laser with integrated photo diodes are shown in Figure 4.

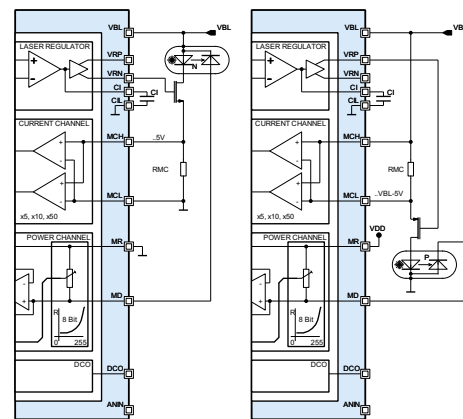


Figure 4: Example of ACC monitoring the optical power $EACC = 1$. In the left setup $MCVR = 0$ and $EPNNP = 0$ while in the right setup, $MCVR = 1$ and $EPNNP = 1$

More examples of configurations for this application on page 34.

Depending on the type of laser, N or P, bit EPNNP has to be set to '0' or '1'.

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| EPNNP | | Addr. 0x13; bit 7 | R/W 0 |
|-------|--------------|-------------------|-------|
| Code | Function | | |
| 0 | N-type laser | | |
| 1 | P-type laser | | |

Table 12: Enable P- or N- type laser

The monitor current is measured via its voltage drop across the internal 8-bit programmable logarithmic resistor PLR (more information about the PLR on page 19). If an external resistor shall be used, it must be connected to pins MD and MR and the internal resistor PLR must be disconnected by setting bit DISP to '1'.

| DISP | | Addr. 0x10; bit 2 | R/W 0 |
|------|--------------|-------------------|-------|
| Code | Function | | |
| 0 | PLR enabled | | |
| 1 | PLR disabled | | |

Table 13: Enable/disable PLR

To measure the optical power, register ADCC(2:0) has to be set to 0b011. Thus the internal voltage MDL = $|V_{MD} - V_{MR}|$ will be selected as an input for the 10-bit A/D converter.

| ADCC(2:0) | | Addr. 0x10; bit 7:5 | R/W 000 |
|-----------|--|---------------------|---------|
| Code | Function | | |
| 000 | ADC sourced by $V(VDD) \div 8$ (3 .. 5.5V) | | |
| 001 | ADC sourced by $V(VBL) \div 30$ (3 .. 24V) | | |
| 010 | ADC sourced by $V(VB) \div 30$ (3 .. 24V) | | |
| 011 | ADC sourced by $V(MDL)$ (0 .. 1.1V) | | |
| 100 | ADC sourced by $V(MC)$ (0 .. 1.1V) | | |
| 101 | ADC sourced by $V(VRN) \div 30$ (0 .. 24V) | | |
| 110 | ADC sourced by $V(VRP) \div 30$ (0 .. 24V) | | |
| 111 | ADC sourced by $V(ANIN)$ (0 .. 1.1V) | | |

Table 14: ADC source selection

APC mode

In APC mode, the optical laser power is controlled. APC mode is selected by setting bit EACC to '0'. In this mode, the monitor diode current is used as feedback in the laser power control loop. To introduce the monitor diode current in to the feedback control loop pins MR and MD are used. An internal, 8-bit programmable logarithmic monitor resistor (PLR) can be used in APC mode and is controlled by register RMD(7:0). It is also possible to use an external monitor resistor connected to pins MR and MD. If register bit DISP is '0', the PLR is present. If DISP is '1', the PLR is disabled and an external monitor resistor must be used. The PLR feature a wide logarithmic resistor range from 100Ω to 500kΩ in steps of typically 3.3%. This covers a wide range of monitor currents. More information about the PLR on page 19.

For fine-tuning the optical power, the reference voltage is set with a 10-bit logarithmic D/A converter, which is configurable using register REF(9:0).

| REF(9:8) | | Addr. 0x13; bit 1:0 | R/W 0x000 |
|----------|--|---------------------|-----------|
| REF(7:0) | | Addr. 0x14; bit 7:0 | R/W 0x000 |
| Code | Function | | |
| 0x000 | Regulator reference voltage set to minimum voltage | | |
| ... | Regulator reference voltage set to | | |
| | $V_{ref} = V_{ref0} (1 + \frac{\Delta V_{ref}(\%)}{100})^{n+1}$, n from 0 to 1023 | | |
| 0x3FF | Regulator reference voltage set to maximum voltage | | |

Table 15: Channel regulator voltage reference

With EPNNP = 1 there is a signal level converter in the control loop, which references the values coming from the PLR to GND. This is necessary because the logarithmic D/A is referenced to GND. In addition this signal level converter adds a 1:2 ratio between the voltage at PLR and at the logarithmic D/A converter i.e. 1.1V at the logarithmic D/A are 0.55V at the PLR.

This converter has a voltage range that goes typically from $V_{ref0} = 0.1$ to $V_{refmax} = 1.1V$, allowing an operation resolution of typically $\Delta V_{ref} = 0.235\%$. More information on the logarithmic D/A converted on page 20. For calculating the minimum value for the monitor feedback current (I_{mon}), $V_{ref}(0x00, \text{max. value})$ (cf. *Electrical Characteristics No. 304*) and $R_{mda}(RMDx = 0xFF, \text{min. value})$ (cf. *Electrical Characteristics No. 201*) are used.

$$I_{mon}(min) = \frac{V_{ref}(0x00, \text{max})}{n \times R_{mda}(RMDx = 0xFF, \text{min})} = \frac{0.11}{350000} = 0.31 \mu A$$

n = 2 for EPNNP = 1
n = 1 for EPNNP = 0

To calculate the maximum value of I_{mon} , $V_{ref}(0x3FF, \text{min. value})$ (cf. *Electrical Characteristics No. 304*) and $R_{mda}(RMD(7:0) = 0x00, \text{max. value})$ (cf. *Electrical Characteristics No. 201*) are used. The following formula is used to calculate $R_{mda}(RMD(7:0) = 0x00, \text{max. value})$:

$$I_{mon}(max) = \frac{V_{ref}(0x3FF, \text{min})}{n \times R_{mda}(RMD = 0x00, \text{max})} = \frac{1.00}{280} = 3.5 \text{ mA}$$

n = 2 for EPNNP = 1
n = 1 for EPNNP = 0

Any other I_{mon} value can be calculated using the Rmd formula above. Due to its logarithmic characteristic, the steps between two consecutive values is kept typically within 3.3% of the nominal value. This formula provide only an approximated value of the resistor. Because of the coupling factor between laser and photodiode and

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the parametric variation of the PLR, each system has to be calibrated separately.

iC-HTG is optimized for driving P-type and N-type laser diodes. Figure 5 shows two examples of driving P-type and N-type laser diodes using APC mode. More examples of possible configurations on page 34.

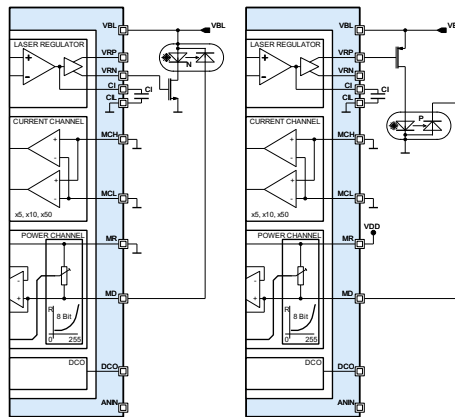


Figure 5: APC with N-channel and P-channel output transistor using N-type and P-type laser diodes. EACC = 0, MCVR = 0, EPNNP = 0 for N-type lasers or EPNNP = 1 for P-type lasers

APC mode monitoring the laser current

In APC mode, there is the possibility to monitor the laser current using the 10-bit linear A/D converter and/or to use the overcurrent monitor function. More about overcurrent on page 17. To measure the optical power, a shunt resistor must be connected to pins MCH/MCL and the register ADCC(2:0) has to be set to 0b100.

| ADCC(2:0) | Addr. 0x10; bit 7:5 | R/W 000 |
|-----------|---|---------|
| Code | Function | |
| 000 | ADC sourced by $V(VDD) \div 8$ (3 .. 5.5 V) | |
| 001 | ADC sourced by $V(VBL) \div 30$ (3 .. 24 V) | |
| 010 | ADC sourced by $V(VB) \div 30$ (3 .. 24 V) | |
| 011 | ADC sourced by $V(MDL)$ (0 .. 1.1 V) | |
| 100 | ADC sourced by $V(MC)$ (0 .. 1.1 V) | |
| 101 | ADC sourced by $V(VRN) \div 30$ (0 .. 24 V) | |
| 110 | ADC sourced by $V(VRP) \div 30$ (0 .. 24 V) | |
| 111 | ADC sourced by $V(ANIN)$ (0 .. 1.1 V) | |

Table 16: ADC source selection

Thus, the internal voltage $MC = V(MCH) - V(MCL)$ will be selected as an input for the 10-bit A/D converter.

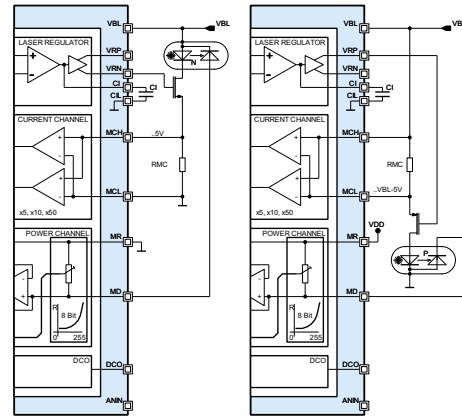


Figure 6: Example of APC monitoring the laser current. EACC = 0. Left: MCVR = 0, EPNNP = 0. Right: MCVR = 1, EPNNP = 1

More configuration examples on page 34.

Other functions

For some special applications (for example with low VB/VBL) it is useful to drive VRN up to VBL. In this case, the register bit VRNHR has to be set to '1'. The default and recommended value is setting the register bit VRNHR to '0'.

| VRNHR | Addr. 0x13; bit 4 | R/W 0 |
|-------|---------------------------|-------|
| Code | Function | |
| 0 | VRN set from 0V to VBL-1V | |
| 1 | VRN set from 1V to VBL | |

Table 17: VRN voltage range

Some applications might need an extra amplification stage after VRN/VRP with inversion of the polarity of the control. For such application, the register bit NSW is to be set to '0' and the polarity of the controller inverted.

| NSW | Addr. 0x13; bit 6 | R/W 1 |
|------|--|-------|
| Code | Function | |
| 0 | Inverted control mode (reference connected to negative input of regulator) | |
| 1 | Standard control mode (reference connected to positive input of regulator) | |

Table 18: CI regulator reference swap

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OVERCURRENT MONITOR

A programmable overcurrent shutdown can be set to protect the laser by disabling the channel. If the voltage drop at the external shunt resistor $V(MCH) - V(MCL)$ is higher than the programmed value the overcurrent signal, OVC, is set and the laser channel is disabled. The maximum voltage drop at the shunt resistor can be programmed using the register ILIM(7:0).

| ILIM(7:0) | | Addr. 0x11; bit 7:0 | R/W 0x00 |
|-----------|---|---------------------|----------|
| Code | Function | | |
| 0x00 | Overcurrent detection disconnected. | | |
| 0x01 | Minimum value of $V(MCH)-V(MCL)$ set to minimum value typ. (0.1V/CGAIN) | | |
| ... | | | |
| 0xFF | Maximum value of $V(MCH)-V(MCL)$ set to maximum value typ. (1.1V/CGAIN) | | |

Table 19: ILIM overcurrent register

An overcurrent event can be simulated using SOVC. If $SOVC = 1$ and the overcurrent detection is enabled (ILIM not set to 0x00), the corresponding overcurrent error bit OVC is set to 1, the error is signaled at NCHK, and the laser channel is disabled. The overcurrent error will remain forced until $SOVC = 0$.

| SOVC | | Addr. 0x16; bit 5 | R/W 0 |
|------|------------------------------------|-------------------|-------|
| Code | Function | | |
| 0 | No overcurrent event is simulated. | | |
| 1 | Overcurrent event simulated. | | |

Table 20: Simulate overcurrent

WATCHDOG TIMER

The internal 200 kHz oscillator is monitored with a watchdog timer (WDT).

If the oscillator remains longer than the maximum time of tWDT (cf. *Electrical Characteristics No. E03*) without activity, an oscillator error is triggered. An oscillator error sets OSCERR error bit to '1'. The automatic off-set compensation of the laser control (see page 13) requires the oscillator.

The state of OSCERR is signaled at pin NCHK. The signaling of OSCERR state can be masked with bit MOSCERR. Setting MOSCERR to '1' masks the oscillator error and in this case OSCERR is not signaled at NCHK.

It is possible to simulate an error of the oscillator using bit SOSCERR. If $SOSCERR = 1$, the oscillator error is forced. When OSCERR is set to '1', the error is signaled through NCHK depending on the state of MOSCERR.

| OSCERR | | Addr. 0x00; bit 6 | R |
|--------|---|-------------------|---|
| Code | Function | | |
| 0 | Oscillator functioning OK | | |
| 1 | Watchdog timeout set on oscillator failure. Cleared on read | | |

Table 21: Oscillator watchdog

| MOSCERR | | Addr. 0x16; bit 0 | R/W 0 |
|---------|--|-------------------|-------|
| Code | Function | | |
| 0 | Oscillator error (watchdog) will be signaled at NCHK | | |
| 1 | Oscillator error (watchdog) will not be signaled at NCHK | | |

Table 22: Oscillator watchdog error mask

| SOSCERR | | Addr. 0x16; bit 7 | R/W 0 |
|---------|--|-------------------|-------|
| Code | Function | | |
| 0 | No oscillator error simulated. | | |
| 1 | Oscillator error simulated (watchdog timeout). | | |

Table 23: Simulate oscillator error

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SERIAL COMMUNICATION INTERFACES

Communication modes

iC-HTG can be configured via a serial interface. It has two communication modes: SPI and I²C. Selection of the communication protocol is achieved using pin INS: INS = hi for I²C, INS = lo for SPI. If the pin INS is left open, NCHK will be pulled to 0.

SPI slave interface

The SPI slave interface is enabled by setting pin INS to lo and the interface uses pins NCS/A1, SCLK/SCL, MISO/SDA and MOSI/A0. The pin NCS/A1 is the chip select pin and must be set lo by the SPI master in order to start communication. The pins MISO/SDA and MOSI/A0 are the data communication lines and pin SCLK/SCL is the clock line generated by the SPI mas-

ter (e.g. a microcontroller). The SPI protocol frames are shown in Figure 7.

A communication frame consists of one address byte and at least one data byte. The bits 7:6 of the address byte are the opcode used for selecting a read operation (set to "10") or a write (set to "01") operation. The remaining 6 bits are used for register addressing.

It is possible to transmit several bytes consecutively if the NCS signal is not reset and SCLK/SCL keeps clocking, as is shown in Figure 7. The address is internally incremented after each transmitted byte. Once the address reaches the last register (0x3F), it is reset back to 0x00.

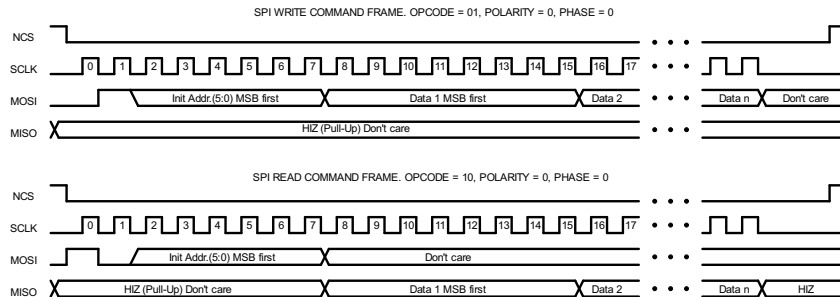


Figure 7: SPI commands

| Action | b7 | b6 | b5 | b4 | b3 | b2 | b1 | b0 |
|-----------------|----|----|----|----|----|----|----|----|
| Write to slave | 1 | 0 | 1 | 0 | ID | A1 | A0 | 0 |
| Read from slave | 1 | 0 | 1 | 0 | ID | A1 | A0 | 1 |

Table 24: I²C write/read byte

I²C slave interface

The I²C slave interface is enabled by setting pin INS to hi and the interface uses pins NCS/A1, SCLK/SCL, MISO/SDA, ID, and MOSI/A0. The protocol frames are shown in Figure 8.

A communication frame consists of one slave address byte, one register address byte, and at least one data byte. The bits 7:1 of the slave address byte are build from the slave identification code (ID) and the address bit A1 and A0. Bit 0 is used to specify the data direction (RNW: 1 for read, 0 for write).

The four most significant bits are fixed by default to the value 0b1010. Pins MOSI/A0, NCS/A1, and ID are

used to set the remaining slave ID bits (see Tables 24 and 25).

| Action | ID | A1 | A0 | Slave ID | Command byte |
|-------------------|----|----|----|----------|--------------|
| Write to slave 0 | lo | lo | lo | 0x50 | 0xA0 |
| Read from slave 0 | lo | lo | lo | 0x50 | 0xA1 |
| Write to slave 1 | lo | lo | hi | 0x51 | 0xA2 |
| Read from slave 1 | lo | lo | hi | 0x51 | 0xA3 |
| Write to slave 2 | lo | hi | lo | 0x52 | 0xA4 |
| Read from slave 2 | lo | hi | lo | 0x52 | 0xA5 |
| Write to slave 3 | lo | hi | hi | 0x53 | 0xA6 |
| Read from slave 3 | lo | hi | hi | 0x53 | 0xA7 |
| Write to slave 4 | hi | lo | lo | 0x54 | 0xA8 |
| Read from slave 4 | hi | lo | lo | 0x54 | 0xA9 |
| Write to slave 5 | hi | lo | hi | 0x55 | 0xAA |
| Read from slave 5 | hi | lo | hi | 0x55 | 0xAB |
| Write to slave 6 | hi | hi | lo | 0x56 | 0xAC |
| Read from slave 6 | hi | hi | lo | 0x56 | 0xAD |
| Write to slave 7 | hi | hi | hi | 0x57 | 0xAE |
| Read from slave 7 | hi | hi | hi | 0x57 | 0xAF |

Table 25: I²C write/read command byte

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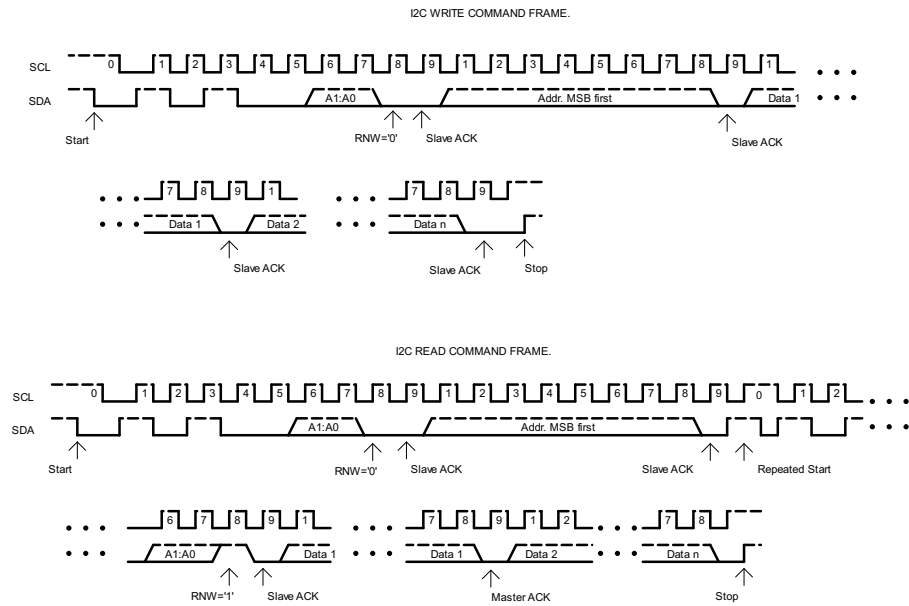


Figure 8: I²C commands

8-BIT INTERNAL PROGRAMMABLE LOGARITHMIC MONITOR RESISTORS

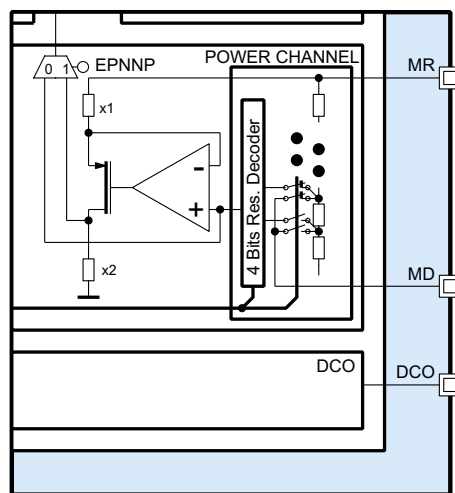


Figure 9: PLR internal node control

An internal 8-bit programmable logarithmic monitor resistor (PLR) is provided for the APC.

The PLR is used to control the optical power of the laser diode in APC mode or to measure a monitor photocurrent in ACC mode using the internal A/D converter. The resistor is connected to pins MR and MD using a force & sense switch structure. This ensures a low thermal dependency and a monotone dependence on the resistor with the register value RMD(7:0). Direct measuring of the internal resistor at pins MD/MR is not possible (see Figure 9).

| RMD(7:0) | Addr. 0x12; bit 7:0 | R/W 0xFF |
|----------|---|----------|
| Code | Function | |
| 0x00 | PLR set to the minimum resistance | |
| ... | PLR set to | |
| | $Rmd = Rmd_0(1 + \frac{\Delta Rmd(\%)}{100})^{n+1}$, n from 0 to 255 | |
| 0xFF | PLR resistor set to the maximum resistance | |

Table 26: MR-MD resistance selection

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The internal resistor value can be selected from 256 values, ranging from typ. $R_{md0} = 100 \Omega$ to over 407 k Ω , following logarithmic increments with a typical step width of $\Delta R_{md} = 3.3\%$. The resistors are configured with register RMD(7:0).

The following formula calculates the register RMD(7:0) in order to set the desired resistor value:

$$R_{md} = R_{md0} \left(1 + \frac{\Delta R_{md}(\%)}{100} \right)^{n+1}, \quad n \in [0, 255],$$

Where R_{md0} is the minimum resistor value (typically 100 Ω), $\Delta R_{md}(\%)$ is the step between two consecutive resistor values (typically 3.3%) and n is the decimal value of register RMD(7:0).

Since the PLR has parametric variations and covers a wide range of resistors values, the given formula is only for simulation or information purposes. Each system needs to be individually calibrated. The recommended procedure is to enable the channel with a high value of RMD(7:0) and a medium value on register REF(9:0). While measuring the optical power, the PLR value is re-

duced until the desired optical power is reached. Then using the register REF(9:0) you can make a more accurate selection of the optical power. For more information see page 13.

The PLR can be disabled via DISP.

| DISP | | Addr. 0x10; bit 2 | R/W 0 |
|------|--------------|-------------------|-------|
| Code | Function | | |
| 0 | PLR enabled | | |
| 1 | PLR disabled | | |

Table 27: Enable/disable PLR

In ACC mode the PLR is not part of the control circuit. Even though the PLR is not in the control circuit, it can be enabled (DISP = 0) in order to give feedback using the 10-bit A/D converter to monitor the optical power, if a monitor diode is connected.

Alternatively, an external monitor resistor can be used to measure the optical power, which requires DISP to be set to '1'.

10-BIT LOGARITHMIC D/A CONVERTER

The 10-bit logarithmic D/A converter is used for setting the regulator's voltage reference. The D/A converter is active in all operating modes. With a range from 0.1 to 1.1 V and the typical step width of $\Delta V_{ref} = 0.235\%$ (maximum $\Delta V_{ref} = 1\%$). This ensures that with each LSB step there is a maximum change of 1% of the optical power.

The D/A converter is configured by REF(9:0). With REF(9:0) = 0x000 the D/A output value is set to 0.1 V and with REF(9:0) = 0x3FF to 1.1 V.

| REF(9:8) | | Addr. 0x13; bit 1:0 | R/W 0x000 |
|----------|---|---------------------|-----------|
| REF(7:0) | | Addr. 0x14; bit 7:0 | R/W 0x000 |
| Code | Function | | |
| 0x000 | Regulator reference voltage set to minimum voltage | | |
| ... | Regulator reference voltage set to | | |
| | $V_{ref} = V_{ref0} \left(1 + \frac{\Delta V_{ref}(\%)}{100} \right)^{n+1}$, n from 0 to 1023 | | |
| 0x3FF | Regulator reference voltage set to maximum voltage | | |

Table 28: Channel regulator voltage reference

To calculate the D/A converter value for each REF(9:0) value, use the following equation.

$$V_{ref} = V_{ref0} \left(1 + \frac{\Delta V_{ref}(\%)}{100} \right)^{n+1}, \quad n \in [0, 1023]$$

Where V_{ref0} is the minimum value (typically 0.1 V), $\Delta V_{ref}(\%)$ is the step value (typically 0.235%) and n is the decimal value of register REF.

Since the D/A has parametric variations, the given formula is only for simulation or information purposes. Each system has to be individually calibrated. The recommended procedure in APC mode is to enable the channel with a high value of RMD(7:0) and a medium value of REF(9:0). While measuring the optical power, reduce the PLR value until the desired optical power is reached. Then, using REF(9:0), you can make a more accurate selection of the optical power.

For ACC mode it is recommended to enable the laser with an appropriate value of REF(9:0). While measuring the optical power, increase the value of REF(9:0), until the desired optical power is reached. For more information see page 13.

Linear mode

The reference voltage for the control can be chosen from a 10 bit logarithmic DAC or a 10 bit Linear DAC with the LINLOG register. In the linear mode (LINLOG = 1), if the ADC is enabled, some noise might be present, since the reference for the control will be sampled and held during the ADC conversion cycle.

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| LINLOG | | Addr. 0x16; bit bit 3 | R/W 0 |
|--------|---------------------------------|-----------------------|-------|
| Code | Function | | |
| 0 | Logarithmic 10 bit DAC selected | | |
| 1 | Linear 10 bit DAC selected | | |

Table 29: Linear or Logarithmic reference selection

| LINLOG | OVC |
|--------|-----------------|
| 0 | Normal function |
| 1 | Disabled |

Table 30: Overcurrent detection in Linear/Logarithmic Mode

LINLOG also affects the overcurrent detection.

10-BIT LINEAR A/D CONVERTER

A 10-bit linear A/D converter is available for a variety of voltages that can be measured with different resolutions:

- V(VDD) up to 5.5 V with 8.6 mV resolution
- V(VBL) up to 30 V with 32.3 mV resolution
- V(VB) up to 30 V with 32.3 mV resolution
- V(MDL) internal voltage up to 1.1 V with 1.075 mV resolution
- V(MC) internal voltage up to 1.1 V with 1.075 mV resolution
- V(VRN) up to 30 V with 32.3 mV resolution
- V(VRP) up to 30 V with 32.3 mV resolution
- V(ANIN) up to 1.1 V with 1.075 mV resolution

As described in block diagram on Page 1, the voltages V(VDD), V(VBL), V(VB), V(VRN), V(VRP) and V(ANIN) are the PIN Voltage directly. V(MC) is proportional to the laser current value and is the voltage difference between pins MCH and MCL ($V(MC) = V(MCH) - V(MCL)$). The voltage V(MDL) is proportional to the optical laser power (monitor current) and the value is the absolute value of the difference between the pins MD and MR ($V(MDL) = |V(MD) - V(MR)|$).

The register ADCC(2:0) select the signal measured with the 10-bit A/D converter.

| ADCC(2:0) | | Addr. 0x10; bit 7:5 | R/W 000 |
|-----------|--|---------------------|---------|
| Code | Function | | |
| 000 | ADC sourced by V(VDD) ÷ 8 (3 .. 5.5 V) | | |
| 001 | ADC sourced by V(VBL) ÷ 30 (3 .. 24 V) | | |
| 010 | ADC sourced by V(VB) ÷ 30 (3 .. 24 V) | | |
| 011 | ADC sourced by V(MDL) (0 .. 1.1 V) | | |
| 100 | ADC sourced by V(MC) (0 .. 1.1 V) | | |
| 101 | ADC sourced by V(VRN) ÷ 30 (0 .. 24 V) | | |
| 110 | ADC sourced by V(VRP) ÷ 30 (0 .. 24 V) | | |
| 111 | ADC sourced by V(ANIN) (0 .. 1.1 V) | | |

Table 31: ADC source selection

| DRDY | | Addr. 0x07; bit bit 0 | R |
|------|---------------------------------|-----------------------|---|
| Code | Function | | |
| 0 | No new ADC data since last read | | |
| 1 | New ADC data available | | |

Table 32: ADC data ready

| ENADCDIV | | Addr. 0x16; bit bit 2 | R/W 1 |
|----------|-------------------------------------|-----------------------|-------|
| Code | Function | | |
| 0 | ADC input voltage dividers disabled | | |
| 1 | ADC input voltage dividers enabled | | |

Table 33: ADC voltage dividers enable

When enabled, the A/D converter is continuously acquiring the signal selected by register ADCC. The conversion time is 140 μs. Changing the source with ADCC may require up to 500 μs settling time of the sampling capacitors. Every time a conversion is finished, the bit DRDY is set. The MCU can poll the DRDY register and when a conversion is ready, read the correspondent data registers. The DRDY registers are clear when read and set back to one after a new conversion is ready.

Sampling input signals at a certain moment

To perform a conversion of an input signal at a certain moment (sampling), procedure can be as follows:

1. Enable the input voltage dividers (ENADCDIV = 1). Set ADCC to the desired input source and wait for the settling time (up to 500 μs).
2. Disable ADC (ENAD = 0). This will cause DRDY to be cleared.
3. Enable ADC at the desired measurement moment to hold the input signal (ENAD = 1).
4. Poll DRDY register until set to one and read ADC data.
5. Repeat from 2.

As the A/D converter is 10 bit long, the results are split into two byte wide separated registers; ADCh contains channel x ADC MSBs values while ADCl stores the LSBs. The A/D converter must be stopped before the

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result can be read to prevent measurement change during MSB and LSB readout. The procedure is as follows:

1. Enable if not already the input voltage dividers (ENADCDIV set to 1), set ADCC to the desired input source with the ADC disabled (ENAD set to 0) and wait for the settling time (Item. 701, up to 500us)
2. Start ADC conversion (ENAD set to 1).
3. Wait for DRDY set to 1.
4. Stop the ADC (ENAD set to 0).
5. Read the ADC data.
6. If ADC input source doesn't need to be changed, repeat from 2.

If the ADC converter is not to be used, the input voltage dividers can be disconnected to save some current (ENADCDIV set to 0).

The voltage corresponding to the measured digital value can be directly obtained using the following formula:

$$V(VBL, VB, VRP, VRN) = 30 * \frac{VFS}{1024} * ADCx$$

$$V(VDD) = 8 * \frac{VFS}{1024} * ADCx$$

$$V(MDL, MC, ANIN) = \frac{VFS}{1024} * ADCx$$

VFS is the full scale voltage of the A/D converter (cf. *Electrical Characteristics No. 706*) typically 1.1V. For a more precise measurement the A/D converter can be calibrated by measuring a known VB voltage and calculating the VFS.

| ADC(9:8) | Addr. 0x03; bit 1:0 | R |
|----------|---------------------|---|
| ADC(7:0) | Addr. 0x04; bit 7:0 | R |
| 0x000 | ADC minimum value | |
| ... | | |
| 0x3FF | ADC maximum value | |

Table 34: ADC

ANIN GENERAL PURPOSE IO PIN

The Pin ANIN is a general purpose IO Pin. Figure 10 describes the functionality of pin ANIN.

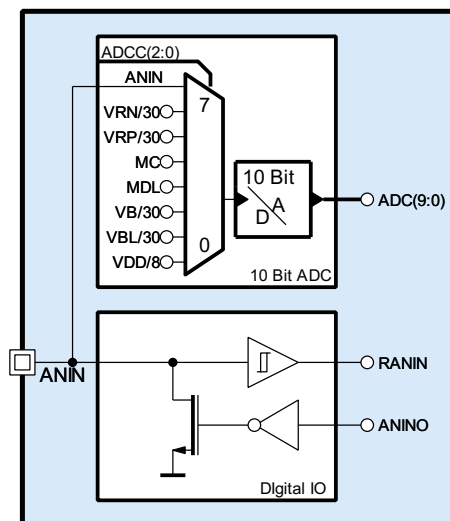


Figure 10: ANIN pin function description

With the pin ANIN an external analog voltage from 0 to 1.1 V can be digitized using the 10 bit linear A/D con-

verter. To this end register bit ANINO has to be set to 1 and the register ADCC(2:0) has to be set to value 0x07. For the digitizing higher voltages a resistor divider is recommended. An example of measuring voltages up to 24 V is shown in Figure 13.

ANIN can be used as a digital open collector output. As digital output an external pull-up resistor needs to be used. The maximum allowed voltage at pin ANIN is 5V. With register bit ANINO the state of ANIN will be set.

| ANINO | Addr. 0x1C; bit 2 | R/W 1 |
|-------|--------------------------------------|-------|
| Code | Function | |
| 0 | ANIN pin pulled low (open collector) | |
| 1 | ANIN pin set to high impedance | |

Table 35: ANIN output state

| RANIN | Addr. 0x01; bit 4 | R |
|-------|---|---|
| Code | Function | |
| 0 | ANIN pin is digital low at the precise reading moment. | |
| 1 | ANIN pin is digital high at the precise reading moment. | |

Table 36: ANIN pin state

As digital TTL input the pin ANIN is mapped to status register bit RANIN.

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DC/DC CONVERTER OPTIMIZATION

iC-HTG provides a 6-bit configurable current source at pin DCO that can be used to trim the output voltage of a DC/DC converter. Current at DCO can be programmed with register RDCO(5:0). In standby mode, DCO current source is disconnected and set to high impedance. Possible application benefits with using DCO include:

- DC/DC step down operation: control at voltages lower than power supply
- DC/DC step up operation: control at voltages higher than power supply
- Efficiency enhancement

| RDCO(5:0) | | Addr. 0x15; bit 5:0 | R/W 0x00 |
|-----------|---------------------------------|---------------------|----------|
| Code | Function | | |
| 0x00 | No current | | |
| ... | | | |
| 0x3F | 130 µA Typ (see spec point D01) | | |

Table 37: DCO current control

The proposed applications can be demonstrated with a standard DC/DC converter, e.g. TPS63060DSC from Texas Instruments. This converter allows an input voltage ranging from 2.5 to 12 V and offers an output voltage ranging from 2.5 to 8 V. It is capable of delivering up to 2 A of current, depending on the output voltage. Figure 11 shows a possible configuration.

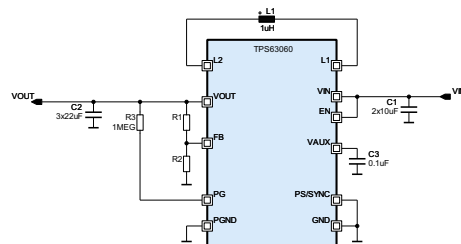


Figure 11: TPS63060 DC/DC converter from TI

DC/DC step down operation: control at voltages lower than power supply

The resistors R1 and R2 in the feedback path allow setting the desired output value Vout. The DC/DC converter drives Vout pin in order to yield 0.5 V at feedback pin FB. The DCO output signal from iC-HTG is connected to pin FB. Vout is controlled with the internal register RDCO(5:0) from iC-HTG.

The DCO current into FB controls the voltages of the divider R1 and R2 and Vout changes in order to maintain

0.5V at the pin FB. When selecting R1 and R2, one needs to consider:

- Resistors values: $R1 = R2 \left(\frac{V_{out}}{V_{FB}} - 1 \right)$
- The current of the voltage divider should be high enough in comparison to the current from the pin DCO to offer acceptable resolution. The programmable current resolution of register RDCO(5:0) is 2 µA.
- The DCO current into the voltage divider lowers the voltage Vout. Vout is 8 V when no current is present at DCO.

Choosing R1 = 100 kΩ, the value of R2 can be calculated to:

$$R2 = \frac{R1}{\frac{V_{out}}{V_{FB}} - 1} = \frac{100k}{\frac{8V}{0.5V} - 1} = 6.7k\Omega$$

With this configuration, the current through the voltage divider is 75 µA at 8 V. The resolution of each RDCO(5:0) step is then 200 mV.

The value in RDCO(5:0) register needed in order to have the desired output voltage can be calculated using the following formula:

$$RDCO = \frac{I_{dco}}{2\mu A} = \frac{IR2 - IR1}{2\mu A} = \frac{0.5V}{8.7V} \frac{V_{out} - 0.5V}{2\mu A}$$

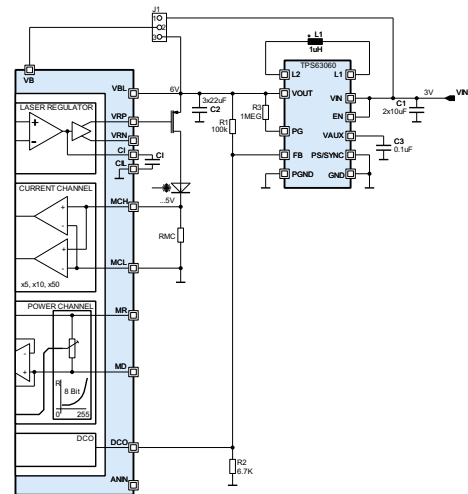


Figure 12: Control of VB/VBL Supply using DCO

The resulting value varies slightly depending on the tolerances of the selected resistors and the DCO current. iC-HTG incorporates an internal 10-bit A/D converter.

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Selecting VBL or VB as input of this converter the supply voltage can be measured and the selected current at DCO can be changed in order to obtain the desired voltage at VBL/VB. Setting register ADCC(2:0) to 0b001 or 0b010, the supply voltages VBL or VB can be measured, respectively. The digitized value is the supply value divided by 30.

DC/DC step up operation: control at voltages higher than power supply

A practical application of the present case is the control of blue lasers. This type of laser presents a forward voltage around 5V, which demands a voltage of about 6V for the anode of the laser diode (LDA). If the system is supplied from a 3V LiPo battery, it is necessary to use a DC/DC in order to step up and drive the laser diode and driver with a sufficient voltage. Figure 12 shows this application. Jumper J1 can be set to 1-2 or 2-3 position.

Typically setting register RDCO(5:0) to 10 it delivers 20 μ A and 6V, which are obtained at Vout.

Extension of system working voltage range

iC-HTG may be supplied with a voltage within the threshold values of 3 and 24V. It is possible to control the DC/DC output in a voltage range of 2.5 to 24V, if the DC/DC converter controlled by the DCO output signal is included in the system, as it is shown in Figure 12.

In Figure 12 both the laser and iC-HTG are supplied with output voltage Vout from DC/DC converter. Typically the register RDCO(5:0) is set to 23, which forces 48 μ A to be output to the voltage divider. A system voltage of 3.3V is obtained at Vout.

Efficiency enhancement

If iC-HTG and the laser diode are supplied with the same power supply, the efficiency of the driver can be improved depending on the supplied voltage, the saturation voltage, and the laser diode forward voltage. The power dissipation of the driver transistor can be reduced if VBL is set through the DC/DC converter configured to deliver a voltage lower than the power supply as shown in Figure 13.

For this application the pin ANIN must be configured as an input by setting the register bit ANINO to 1. Using the resistors RA1 and RA2, the drain voltage at the

drive transistor is reduced by a factor of approximately 30. For more information about ANIN see page 22.

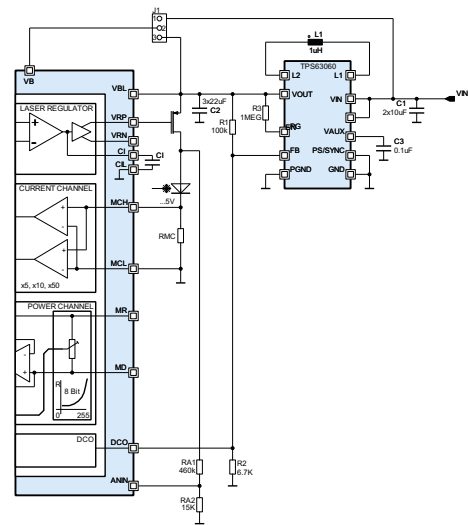


Figure 13: System efficiency enhancement

| ANINO | Addr. 0x1C; bit 2 | R/W 1 |
|-------|--------------------------------------|-------|
| Code | Function | |
| 0 | ANIN pin pulled low (open collector) | |
| 1 | ANIN pin set to high impedance | |

Table 38: ANIN output state

In this configuration, the voltage drop at the driver transistor can be measured and minimized by setting an appropriate supply at VBL. Some steps have to be done to optimize the power dissipation:

1. Measure the voltage at pin VBL, setting the register ADCC(2:0) to 0b001. The measured voltage AD(VBL) is divided by a factor of 30.
2. Measure the voltage at pin ANIN, AD(ANIN).
3. The voltage drop at the driver transistor is $(AD(VBL) - AD(ANIN)) * 30$. By changing the DCO(6:0) register, the supply voltage at V(VBL) can be increased or decreased. ANIN should remain constant.
4. Repeat steps 1 to 3 to achieve the desired voltage drop at the output transistor.

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ANALOG MODULATION

iC-HTG allows analog modulation of the output current at a frequency of up to 50 kHz. An external modulation voltage source (sinusoidal, triangular, etc.) must be provided and connected to pin MOD. The internal control loop forces the laser diode current to follow the modulation voltage signal. This feature is enabled by setting register bit ENAM high.

| ENAM | | Addr. 0x13; bit 3 | R/W 0 |
|------|----------------------------|-------------------|-------|
| Code | Function | | |
| 0 | Analog modulation disabled | | |
| 1 | Analog modulation enabled | | |

Table 39: Enable analog modulation

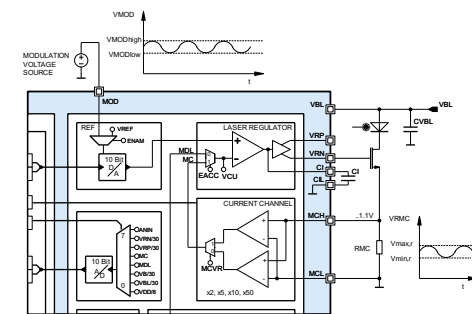


Figure 14: Recommended configuration for analog modulation using N-channel transistor. EACC = 1, MCVR = 0

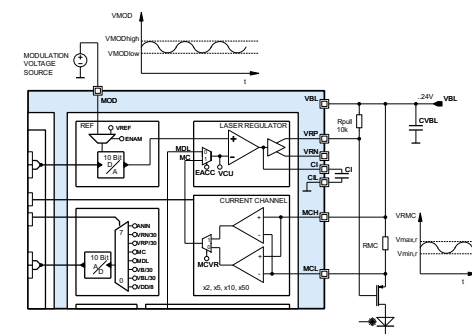


Figure 15: Recommended configuration for analog modulation using P-channel transistor. EACC = 1, MCVR = 1

The maximum allowed modulation frequency is 50 kHz, but general performance depends on the external ca-

pacitor connected at CI, the value of the RMC, the current gain selected (CGAIN(1:0)), and the total gate capacity of the external transistor.

To ensure a higher stability, the configuration shown in Figure 15 is recommended (see Figure 20 left from Examples of configuration on page 34). CGAIN(1:0) must be kept as low as possible, increasing the value of the RMC if necessary. For 50 kHz modulation Figure 15 is recommended with values of CI from 100 to 300 pF.

Setting Current Modulation

The modulation current is set by 4 factors:

- The modulation amplitude at MOD (1.1 V max.)
- The digital-to-analog converter setpoint REF(9:0)
- The external sense resistor RMC
- Current Channel gain CGAIN(1:0).

With the analog modulation VREF is no more a DC voltage for the regulator but a voltage divider for the V(MOD) voltage to downscale AC and DC voltages for the regulator. The V(MOD) voltage contains a DC voltage part and a AC voltage part to define the required operation point with the parameter set.

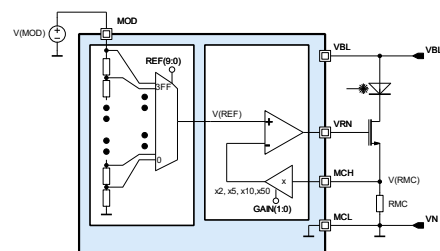


Figure 16: Signal path of the analog modulation

It is not recommended to use lower values than 100 mV for V(REF). For lower voltages the accuracy of the control and the frequency response are not guaranteed. Therefore V(MOD) must be selected according to the REF(9:0) dividing factor to ensure V(REF) higher or equal to 0.1 V.

For a first estimate of the values, the equation (1) and (2) can be used. In this equations REF_x can be 1 to 1023 and CGAIN_x can take the values 2, 5, 10 and 50.

$$(1) V(RMC) = \frac{V(MOD)}{1023} \cdot \frac{REF_x}{CGAIN_x}$$

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$$(2) I(RMC) = \frac{VMOD}{1023} \cdot \frac{REFx}{CGAINx} \cdot \frac{1}{RMC}$$

With this equation the theoretical current value can be calculated. More accurate calculations can be made using the parameters 303 304 and 305 of the Electrical Characteristics and the equation (3) and (4).

$$(3) V(RMC) = \frac{VMOD}{1.1} \cdot \frac{V(REF)}{G()}$$

$$(4) I(RMC) = \frac{VMOD}{1.1} \cdot \frac{V(REF)}{G()} \cdot \frac{1}{RMC}$$

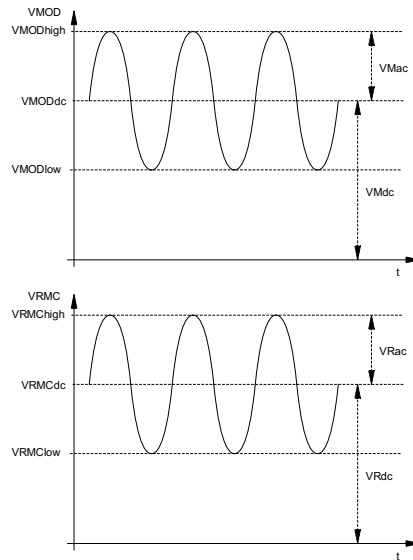


Figure 17: Example of modulation voltages

Due to the parameter variation is recommended to calibrate each circuit. The recommended procedure to set the current modulation values is:

1. Set the GAINx(1:0) value (0x00 is recommended).
2. Set a reference value of voltage in V(MOD). For example a low voltage or a DC voltage (VMODdc) in a sinus signal as shown in figure 17.
3. With a fixed voltage at V(MOD) (for example VMODdc) use REF(9:0) to set the desired

V(RMC) (in this case V(RMCdc) for current laser I(RMCdc)). You can use the internal AD-Converter to sense the voltage at RMC.

Note that using the equation the laser current I(RMCdc) is:

$$(5) I(RMCdc) = \frac{VMODdc}{1.1} \cdot \frac{V(REF)}{G()} \cdot \frac{1}{RMC}$$

4. With this setup the relationship between the voltage at V(MOD) and the referenced current is given by (7):

$$(6) I(RMChigh) = \frac{VMODhigh}{1.1} \cdot \frac{V(REF)}{G()} \cdot \frac{1}{RMC}$$

$$(7) \frac{I(RMChigh)}{I(RMCdc)} = \frac{VMODhigh}{VMODdc}$$

Analog Modulation in APC mode

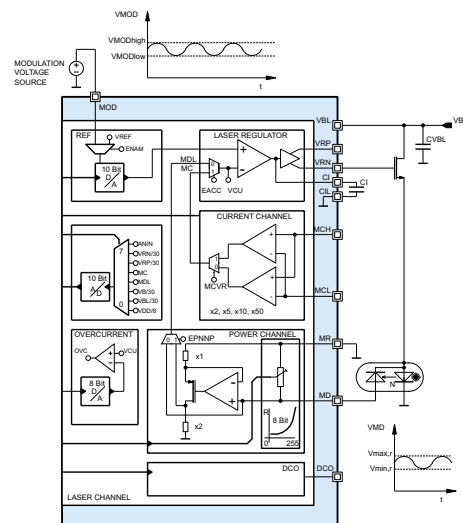


Figure 18: Example of Analog Modulation using APC mode

It is possible to use analog modulation using an APC mode. In this case the stability of the system is more critical and higher CI capacitors (> 1 nF) are recommended. This is depending on laser diode, PCB and logarithmic resistor setting. Only a few kHz are recommended for the analog modulation in APC mode. An example of configuration using analog modulation in APC mode is shown in Figure 18.

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TEMPERATURE MONITOR AND PROTECTION

iC-HTG includes an 8-bit temperature monitor that allows to measure the internal chip temperature going from -40 to 125 °C. The resolution is 1 °C/LSB.

| TEMP(7:0) | | Addr. 0x02; bit 7:0 | R |
|-----------|---------------------|---------------------|---|
| Code | Function | | |
| 0x00 | Minimum temperature | | |
| ... | | | |
| 0xFF | Maximum temperature | | |

Table 40: Chip temperature

Absolute read values may differ from one chip to another. An individual initial calibration of the temperature monitor is recommended. The TEMP register must be read at a known temperature. Using the resolution value of 1 °C/LSB, the internal temperature can be calculated.

The temperature monitor can be used to compensate temperature effects in the laser diode. The microcontroller can use a laser diode characteristic formula or a look-up table combined with the temperature value measured using TEMP register. The reference voltage can be configured accordingly in order to compensate for temperature effects.

iC-HTG is protected against overtemperature. If the internal temperature exceeds a safe value, an overtem-

perature error bit (OVT) is set to 1. If OVT = 1, the laser channel is disabled and the error event is signaled through pin NCHK. The error bit OVT is latched and can only be cleared by reading the status register.

The overtemperature threshold value can not be configured.

| OVT | | Addr. 0x00; bit 3 | R |
|------|---|-------------------|---|
| Code | Function | | |
| 0 | No overtemperature event has occurred since last read | | |
| 1 | Overtemperature event has occurred. Cleared on read | | |

Table 41: Overtemperature

It is possible to simulate an overtemperature event using the bit SOVT. Setting SOVT to 1, the overtemperature error flag OVT is set to 1. iC-HTG remains in the error state until SOVT is set back to 0.

| SOVT | | Addr. 0x16; bit 4 | R/W 0 |
|------|--|-------------------|-------|
| Code | Function | | |
| 0 | No overtemperature event is simulated. | | |
| 1 | Overtemperature event simulated. | | |

Table 42: Simulate overtemperature

CONFIGURATION MODE AND MEMORY INTEGRITY MONITOR

iC-HTG supports the interfaces SPI or I²C, which are selected by the INS pin. More information about the serial communication interface on page 18.

In the configuration mode the iC-HTG configuration can be amended without affecting the configuration stored in the iC-HTG RAM. Only when switching back to the operation mode, the configuration is applied to the iC-HTG in an atomic operation (all at once).

Integrity monitoring is implemented by a duplication of the configuration registers into a validation page (see description below) where the registers are automatically copied with their inverted values. Every register bit is compared with its validation copy and, in case of inconsistency, a memory error is generated and the laser channel is switched off.

Atomic appliance is achieved by latching the configuration registers. This permits a full configuration (different

registers) to be made prior to applying it to the laser channel.

The configuration mode is selected by setting the register MODE(1:0) to 10.

| MODE(1:0) | | Addr. 0x1C; bit 1:0 | R/W 01 |
|-----------|---|---------------------|--------|
| Code | Function | | |
| 00 | Not allowed, signaled as memory error | | |
| 01 | Chip set in operation mode (apply configuration, latch transparent) | | |
| 10 | Chip set in configuration mode (hold previous configuration) | | |
| 11 | Not allowed, signaled as memory error | | |

Table 43: Select configuration or operation mode

In **Configuration mode** the *configuration memory* (addr. 0x10 to 0x1F) can be written and read back to check a correct communication without changing the

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present configured operation state of the iC-HTG. In this mode, the memory integrity check is disabled.

iC-HTG will monitor the time elapsed in configuration mode and automatically switch the laser off, if it exceeds a configuration mode timeout. The time in configuration mode must be less than 40 ms to ensure that no configuration timeout occurs during configuration (cf. *Electrical Characteristics No. E02*).

When writing the configuration is completed, iC-HTG is switched to **operating mode** by writing "01" into the MODE register (addr. 0x1C). In **operating mode** the configuration is applied to the iC-HTG and the memory integrity check activated. In this mode configuration registers can only be read (except MODE(1:0) register, which is always accessible). Figure 19 shows the interface to the memory structure.

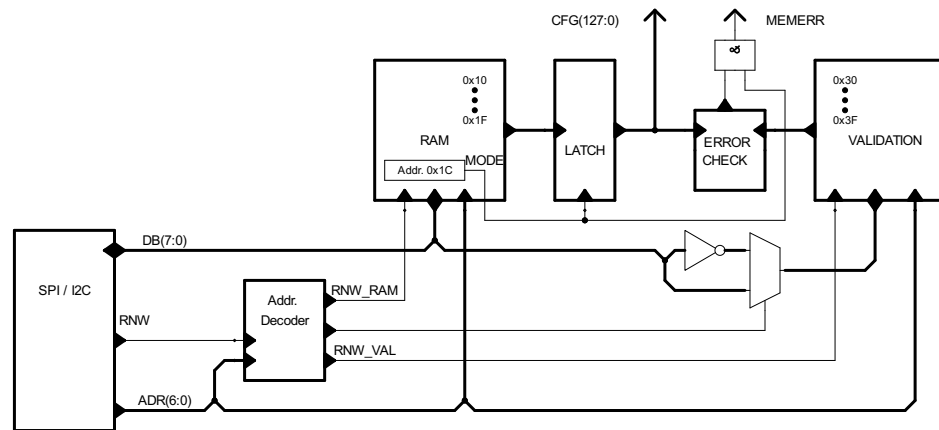


Figure 19: Interface, RAM integrity monitoring, and configuration latching

Register map description

The register map consists of 64 addresses subdivided in three different pages:

- Read-only page, addr. 0x00 to 0x0F: iC-HTG status, ADC readout, temperature sensor readout and chip revision
- Configuration page (integrity monitored), read/write registers, addr. 0x10 to 0x1F
- Validation page, read/write registers, addr. 0x30 to 0x3F

Read-only registers with values or states

The read-only registers are sub-divided into status registers (addr. 0x00 to 0x01) and measurement registers and the chip revision register CHIPREV. Status registers are normally latched to 1 on events and cleared on read (see individual register description). Measurement registers are dual-port and can be accessed simultaneously with the measurements in progress. ADC (addr. 0x03 to 0x04) is a 10-bit register split into two 8-bit registers and must be accessed in block mode (automatic address increment) to ensure data does not change during the read.

Configuration page (integrity monitored)

The configuration page (addr. 0x10 to 0x1F) contains the registers that control the driver. Every write operation to any of the registers of this page will be internally duplicated to the correspondent register at the validation page. After the write operation, the correspondent validation register contains the inverted value of the configuration register.

Validation page

The validation page (addr. 0x30 to 0x3F) can be read or written normally. Only when a write procedure is made to any of the configuration registers, the correspondent validation pair will be written with the inverted value of the configuration register as well.

Both the configuration and validation pages are initialized during power-up. This event is signaled at the STATUS0 register (bit 0, INITRAM). In standby mode (NSTBY = 1) the RAM is not reset if any write command has been executed and therefore configuration and validation pages keep the stored information and INITRAM remains unset. Entering standby mode after power-up without any write command, the RAM will be initialized again and the INITRAM bit will be set to 1

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again. Any VDD power-down event signaled at the STATUS0 register outside the standby mode (NSTBY = hi) requires a RAM content check regardless of the state of the INITRAM bit to ensure data is not corrupted.

Possible start-up sequence:

- iC-HTG starts in operation mode with default configuration. INITRAM and PDOVDD error bits are set in STATUS0, DISC (addr. 0x10, bit 3) is set to 1.
- Write MODE(1:0) = "10" register (addr. 0x1C) to enable the configuration mode.
- Configure the laser channel.
- Read back to verify a correct data transfer.
- Set the DISC bit to 0.
- Read the status registers (addr. 0x00, 0x01) to detect possible errors and validate status. At any error: read again to ensure that the error is valid.
- Write MODE(1:0) = "01" register (addr. 0x1C) to apply the configuration and enable the memory integrity check.
- During operation: monitor the status registers, checking for errors. The pin NCHK signals any set status bit if not masked. This pin can be used to trigger an microcontroller interrupt line.

REGISTER OVERVIEW

| OVERVIEW | | | | | | | | |
|----------|--|--------|-------|-----------|----------|----------|-----------|---------|
| Addr | Bit 7 | Bit 6 | Bit 5 | Bit 4 | Bit 3 | Bit 2 | Bit 1 | Bit 0 |
| 0x00 R | CFGTIMO | OSCERR | OVC | PDOVBL | OVT | MEMERR | PDOVDD | INITRAM |
| 0x01 R | 0 | 0 | 0 | RANIN | NMCOK | EC | MONC | MAPC |
| 0x02 R | TEMP(7:0) | | | | | | | |
| 0x03 R | | | | | ADC(9:8) | | | |
| 0x04 R | ADC(7:0) | | | | | | | |
| 0x05 R | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| 0x06 R | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 |
| 0x07 R | 0 | 0 | 0 | 0 | 0 | 0 | 0 | DRDY |
| 0x08 R | Not implemented | | | | | | | |
| ... | Not implemented | | | | | | | |
| 0x0F R | CHIPREV | | | | | | | |
| 0x10 | ADCC(2:0) | | | 1 | DISC | DISP | ENAD | EACC |
| 0x11 | ILIM(7:0) | | | | | | | |
| 0x12 | RMD(7:0) | | | | | | | |
| 0x13 | EPNNP | NSW | 0 | VRNHR | ENAM | MCVR | REF(9:8) | |
| 0x14 | REF(7:0) | | | | | | | |
| 0x15 | CGAIN(1:0) | | | RDCO(5:0) | | | | |
| 0x16 | SOSCERR | | SOVC | SOVT | LINLOG | ENADCDIV | MMONC | MOSCERR |
| 0x17 | Reserved | | | | | | | |
| 0x18 | Not implemented | | | | | | | |
| 0x19 | Not implemented | | | | | | | |
| 0x1A | Not implemented | | | | | | | |
| 0x1B | Not implemented | | | | | | | |
| 0x1C | Not implemented | | | | | ANINO | MODE(1:0) | |
| 0x1D | Not implemented | | | | | | | |
| 0x1E | Reserved register. Set to zero | | | | | | | |
| 0x1F | Reserved register(Factory test). Set to zero | | | | | | | |
| 0x20 | Not implemented | | | | | | | |
| ... | Not implemented | | | | | | | |

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| OVERVIEW | | | | | | | | |
|----------|---------------------------------------|-------|-------|-------|-------|-------|-------|-------|
| Addr | Bit 7 | Bit 6 | Bit 5 | Bit 4 | Bit 3 | Bit 2 | Bit 1 | Bit 0 |
| 0x30 | Validation content for 0x10, inverted | | | | | | | |
| 0x31 | Validation content for 0x11, inverted | | | | | | | |
| ... | ... | | | | | | | |
| 0x3F | Validation content for 0x1F, inverted | | | | | | | |

Table 44: Register layout

PARAMETERS

| Register | Address | Bits | Description |
|----------|---------|------|---|
| INITRAM | 0x00 | 0 | RAM initialized. |
| PDOVDD | 0x00 | 1 | Power-down event at VDD |
| MEMERR | 0x00 | 2 | RAM memory validation error |
| OVT | 0x00 | 3 | Overtemperature event |
| PDOVBL | 0x00 | 4 | Power-down event at VBL |
| OVC | 0x00 | 5 | Overcurrent |
| OSCERR | 0x00 | 6 | Oscillator error (watchdog set) |
| CFGTIMO | 0x00 | 7 | Configuration mode timeout event |
| MAPC | 0x01 | 0 | Channel state |
| MONC | 0x01 | 1 | Channel enabled at least once (latched) |
| EC | 0x01 | 2 | EC pin digital state |
| NMCOK | 0x01 | 3 | MCL, MCH voltage status |
| RANIN | 0x01 | 4 | ANIN pin digital state |

Table 45: Status overview

| Register | Address | Bits | Description |
|----------|---------|------|------------------------------|
| TEMP | 0x02 | 7:0 | Chip temperature measurement |
| ADCh | 0x03 | 1:0 | ADC 9:8 readout |
| ADCI | 0x04 | 7:0 | ADC 7:0 readout |
| DRDY | 0x07 | 0 | ADC data ready |
| CHIPREV | 0x0F | 7:0 | Chip revision identification |

Table 46: Measurement overview

Status

| PDOVDD | | Addr. 0x00; bit 1 | R |
|--------|--|-------------------|---|
| Code | Function | | |
| 0 | VDD power down not occurred since last read | | |
| 1 | VDD power down event has occurred. Cleared on read | | |

Table 48: VDD power down

| INITRAM | | Addr. 0x00; bit 0 | R |
|---------|-------------------------------------|-------------------|---|
| Code | Function | | |
| 0 | RAM not initialized since last read | | |
| 1 | RAM initialized. Cleared on read | | |

Table 47: RAM initialization

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| MEMERR | | Addr. 0x00; bit 2 | R |
|--------|--|-------------------|---|
| Code | Function | | |
| 0 | RAM has not been changed since last validation | | |
| 1 | RAM has changed and has not been validated | | |

Table 49: Memory validation

| OVT | | Addr. 0x00; bit 3 | R |
|------|---|-------------------|---|
| Code | Function | | |
| 0 | No overtemperature event has occurred since last read | | |
| 1 | Overtemperature event has occurred. Cleared on read | | |

Table 50: Overtemperature

| PDOVBL | | Addr. 0x00; bit 4 | R |
|--------|--|-------------------|---|
| Code | Function | | |
| 0 | VBL power down not occurred since last read | | |
| 1 | VBL power down event has occurred. Cleared on read | | |

Table 51: VBL power down

| OVC | | Addr. 0x00; bit 5 | R |
|------|---|-------------------|---|
| Code | Function | | |
| 0 | No overcurrent event has occurred since last read | | |
| 1 | Overcurrent event has occurred. Cleared on read | | |

Table 52: Overcurrent

| OSCERR | | Addr. 0x00; bit 6 | R |
|--------|---|-------------------|---|
| Code | Function | | |
| 0 | Oscillator functioning OK | | |
| 1 | Watchdog timeout set on oscillator failure. Cleared on read | | |

Table 53: Oscillator watchdog

| CFGTIMO | | Addr. 0x00; bit 7 | R |
|---------|--|-------------------|---|
| Code | Function | | |
| 0 | iC-HTG not in <i>configuration mode</i> or <i>timeout</i> did not happened till now | | |
| 1 | iC-HTG in <i>configuration mode</i> and <i>timeout</i> happened. Laser switched off. | | |

Table 54: Configuration timeout

| MAPC | | Addr. 0x01; bit 0 | R |
|------|--|-------------------|---|
| Code | Function | | |
| 0 | Channel is off at the precise reading moment | | |
| 1 | Channel is on at the precise reading moment | | |

Table 55: Channel state

| MONC | | Addr. 0x01; bit 1 | R |
|------|---|-------------------|---|
| Code | Function | | |
| 0 | Channel has not been switched on since last read | | |
| 1 | Channel has been switched on at least once. Cleared on read | | |

Table 56: Channel state history

| EC | | Addr. 0x01; bit 2 | R |
|------|---|-------------------|---|
| Code | Function | | |
| 0 | EC pin is high at the precise reading moment. | | |
| 1 | EC pin is low at the precise reading moment. | | |

Table 57: EC pin state

| NMCOK | | Addr. 0x01; bit 3 | R |
|-------|--|-------------------|---|
| Code | Function | | |
| 0 | MCH-MCL voltage is OK for the selected laser type. | | |
| 1 | MCH-MCL voltage is not OK for the selected laser type. | | |

Table 58: MCH-MCL voltage status

| RANIN | | Addr. 0x01; bit 4 | R |
|-------|---|-------------------|---|
| Code | Function | | |
| 0 | ANIN pin is digital low at the precise reading moment. | | |
| 1 | ANIN pin is digital high at the precise reading moment. | | |

Table 59: ANIN pin state

| TEMP(7:0) | | Addr. 0x02; bit 7:0 | R |
|-----------|---------------------|---------------------|---|
| Code | Function | | |
| 0x00 | Minimum temperature | | |
| ... | | | |
| 0xFF | Maximum temperature | | |

Table 60: Chip temperature

| DRDY | | Addr. 0x07; bit bit 0 | R |
|------|---------------------------------|-----------------------|---|
| Code | Function | | |
| 0 | No new ADC data since last read | | |
| 1 | New ADC data available | | |

Table 61: ADC data ready

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| CHIPREV | | Addr. 0x0F; bit 7:0 | R |
|---------|-----------|---------------------|---|
| Code | Function | | |
| 16 | iC-HTG 0 | | |
| 17 | iC-HTG 1 | | |
| 18 | iC-HTG Z | | |
| 19 | iC-HTG Z1 | | |
| 20 | iC-HTG Y | | |
| 21 | iC-HTG Y1 | | |
| 22 | iC-HTG X | | |
| 23 | iC-HTG W | | |
| 24 | iC-HTG W1 | | |

Table 62: Chip revision

Channel configuration registers

| EACC | | Addr. 0x10; bit 0 | R/W 0 |
|------|--|-------------------|-------|
| Code | Function | | |
| 0 | APC mode enabled (laser power control) | | |
| 1 | ACC mode enabled (laser current control) | | |

Table 63: Select APC or ACC

| ENAD | | Addr. 0x10; bit 1 | R/W 0 |
|------|---|-------------------|-------|
| Code | Function | | |
| 0 | AD Converter disabled | | |
| 1 | AD Converter enabled, source selected with ADCC | | |

Table 64: Enable ADC

| DISP | | Addr. 0x10; bit 2 | R/W 0 |
|------|--------------|-------------------|-------|
| Code | Function | | |
| 0 | PLR enabled | | |
| 1 | PLR disabled | | |

Table 65: Enable/disable PLR

| DISC | | Addr. 0x10; bit 3 | R/W 1 |
|------|-------------------------------------|-------------------|-------|
| Code | Function | | |
| 0 | Channel can be enabled by pin EC | | |
| 1 | Channel cannot be enabled by pin EC | | |

Table 66: Disable channel

| ADCC(2:0) | | Addr. 0x10; bit 7:5 | R/W 000 |
|-----------|---|---------------------|---------|
| Code | Function | | |
| 000 | ADC sourced by $V(VDD) \div 8$ (3 .. 5.5 V) | | |
| 001 | ADC sourced by $V(VBL) \div 30$ (3 .. 24 V) | | |
| 010 | ADC sourced by $V(VB) \div 30$ (3 .. 24 V) | | |
| 011 | ADC sourced by $V(MDL)$ (0 .. 1.1 V) | | |
| 100 | ADC sourced by $V(MC)$ (0 .. 1.1 V) | | |
| 101 | ADC sourced by $V(VRN) \div 30$ (0 .. 24 V) | | |
| 110 | ADC sourced by $V(VRP) \div 30$ (0 .. 24 V) | | |
| 111 | ADC sourced by $V(ANIN)$ (0 .. 1.1 V) | | |

Table 67: ADC source selection

| ILIM(7:0) | | Addr. 0x11; bit 7:0 | R/W 0x00 |
|-----------|---|---------------------|----------|
| Code | Function | | |
| 0x00 | Overcurrent detection disconnected. | | |
| 0x01 | Minimum value of $V(MCH)-V(MCL)$ set to minimum value typ. (0.1V/CGAIN) | | |
| ... | | | |
| 0xFF | Maximum value of $V(MCH)-V(MCL)$ set to maximum value typ. (1.1V/CGAIN) | | |

Table 68: ILIM overcurrent register

| RMD(7:0) | | Addr. 0x12; bit 7:0 | R/W 0xFF |
|----------|---|---------------------|----------|
| Code | Function | | |
| 0x00 | PLR set to the minimum resistance | | |
| ... | PLR set to | | |
| | $Rmd = Rmd_0(1 + \frac{\Delta Rmd(\%)}{100})^{n+1}$, n from 0 to 255 | | |
| 0xFF | PLR resistor set to the maximum resistance | | |

Table 69: MR-MD resistance selection

| REF(9:8) | | Addr. 0x13; bit 1:0 | R/W 0x000 |
|----------|---|---------------------|-----------|
| REF(7:0) | | Addr. 0x14; bit 7:0 | R/W 0x000 |
| Code | Function | | |
| 0x000 | Regulator reference voltage set to minimum voltage | | |
| ... | Regulator reference voltage set to | | |
| | $Vref = Vref_0(1 + \frac{\Delta Vref(\%)}{100})^{n+1}$, n from 0 to 1023 | | |
| 0x3FF | Regulator reference voltage set to maximum voltage | | |

Table 70: Channel regulator voltage reference

| MCVR | | Addr. 0x13; bit 2 | R/W 0 |
|------|--------------------------------------|-------------------|-------|
| Code | Function | | |
| 0 | MCx Voltage Range is 0 to 5V | | |
| 1 | MCx Voltage Range is VBL – 5V to VBL | | |

Table 71: MCx voltage range

| ENAM | | Addr. 0x13; bit 3 | R/W 0 |
|------|----------------------------|-------------------|-------|
| Code | Function | | |
| 0 | Analog modulation disabled | | |
| 1 | Analog modulation enabled | | |

Table 72: Enable analog modulation

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| NSW | | Addr. 0x13; bit 6 | R/W 1 |
|------|---|-------------------|-------|
| Code | Function | | |
| 0 | Inverted control mode (reference connected to negative input of regulator) | | |
| 1 | Standard control mode (reference connected to positive input of regulator) | | |

Table 73: CI regulator reference swap

| EPNNP | | Addr. 0x13; bit 7 | R/W 0 |
|-------|--------------|-------------------|-------|
| Code | Function | | |
| 0 | N-type laser | | |
| 1 | P-type laser | | |

Table 74: Enable P- or N- type laser

| RDCO(5:0) | | Addr. 0x15; bit 5:0 | R/W 0x00 |
|-----------|---------------------------------|---------------------|----------|
| Code | Function | | |
| 0x00 | No current | | |
| ... | | | |
| 0x3F | 130 µA Typ (see spec point D01) | | |

Table 75: DCO current control

| CGAIN(1:0) | | Addr. 0x15; bit 7:6 | R/W 00 |
|------------|--------------------------|---------------------|--------|
| Code | Function | | |
| 00 | Amplification set to x2 | | |
| 01 | Amplification set to x5 | | |
| 10 | Amplification set to x10 | | |
| 11 | Amplification set to x50 | | |

Table 76: MCx voltage drop amplification

| MOSCERR | | Addr. 0x16; bit 0 | R/W 0 |
|---------|--|-------------------|-------|
| Code | Function | | |
| 0 | Oscillator error (watchdog) will be signaled at NCHK | | |
| 1 | Oscillator error (watchdog) will not be signaled at NCHK | | |

Table 77: Oscillator watchdog error mask

| MMONC | | Addr. 0x16; bit 1 | R/W 1 |
|-------|---|-------------------|-------|
| Code | Function | | |
| 0 | Enable Channel will be signaled at NCHK | | |
| 1 | Enable Channel will not be signaled at NCHK | | |

Table 78: Enable Channel (ENCH) monitor mask

| SOVT | | Addr. 0x16; bit 4 | R/W 0 |
|------|--|-------------------|-------|
| Code | Function | | |
| 0 | No overtemperature event is simulated. | | |
| 1 | Overtemperature event simulated. | | |

Table 79: Simulate overtemperature

| SOVC | | Addr. 0x16; bit 5 | R/W 0 |
|------|------------------------------------|-------------------|-------|
| Code | Function | | |
| 0 | No overcurrent event is simulated. | | |
| 1 | Overcurrent event simulated. | | |

Table 80: Simulate overcurrent

| SOSCERR | | Addr. 0x16; bit 7 | R/W 0 |
|---------|--|-------------------|-------|
| Code | Function | | |
| 0 | No oscillator error simulated. | | |
| 1 | Oscillator error simulated (watchdog timeout). | | |

Table 81: Simulate oscillator error

| ENADCDIV | | Addr. 0x16; bit bit 2 | R/W 1 |
|----------|-------------------------------------|-----------------------|-------|
| Code | Function | | |
| 0 | ADC input voltage dividers disabled | | |
| 1 | ADC input voltage dividers enabled | | |

Table 82: ADC voltage dividers enable

| LINLOG | | Addr. 0x16; bit bit 3 | R/W 0 |
|--------|---------------------------------|-----------------------|-------|
| Code | Function | | |
| 0 | Logarithmic 10 bit DAC selected | | |
| 1 | Linear 10 bit DAC selected | | |

Table 83: Linear or Logarithmic reference selection

| MODE(1:0) | | Addr. 0x1C; bit 1:0 | R/W 01 |
|-----------|---|---------------------|--------|
| Code | Function | | |
| 00 | Not allowed, signaled as memory error | | |
| 01 | Chip set in operation mode (apply configuration, latch transparent) | | |
| 10 | Chip set in configuration mode (hold previous configuration) | | |
| 11 | Not allowed, signaled as memory error | | |

Table 84: Select configuration or operation mode

| ANINO | | Addr. 0x1C; bit 2 | R/W 1 |
|-------|--------------------------------------|-------------------|-------|
| Code | Function | | |
| 0 | ANIN pin pulled low (open collector) | | |
| 1 | ANIN pin set to high impedance | | |

Table 85: ANIN output state

| VRNHR | | Addr. 0x13; bit 4 | R/W 0 |
|-------|---------------------------|-------------------|-------|
| Code | Function | | |
| 0 | VRN set from 0V to VBL-1V | | |
| 1 | VRN set from 1V to VBL | | |

Table 86: VRN voltage range

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EXAMPLES OF CONFIGURATION

ACC mode

Examples of ACC mode using P-channel transistor, Figures 20 and 21.

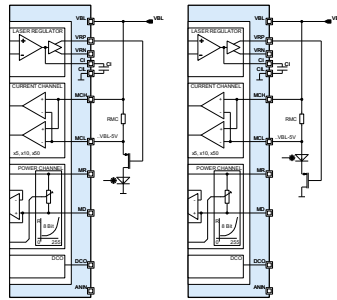


Figure 20: Working in ACC mode with P-channel output transistor as follower. **(Recommended)**

| EACC | MCVR | EPNPP |
|------|------|-------|
| 1 | 1 | - |

Table 87: Register for Figure 20

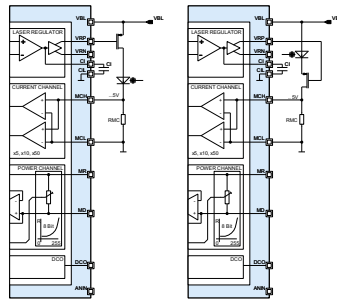


Figure 21: Working in ACC mode with P-channel output transistor

| EACC | MCVR | EPNPP |
|------|------|-------|
| 1 | 0 | - |

Table 88: Register for Figure 21

Examples of ACC Mode using N-channel transistor, Figures 22 and 23.

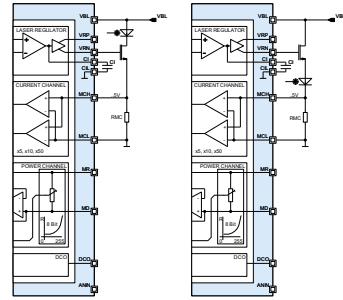


Figure 22: Working in ACC mode with N-channel output transistor as follower. **(Recommended)**

| EACC | MCVR | EPNPP |
|------|------|-------|
| 1 | 0 | - |

Table 89: Register for Figure 22

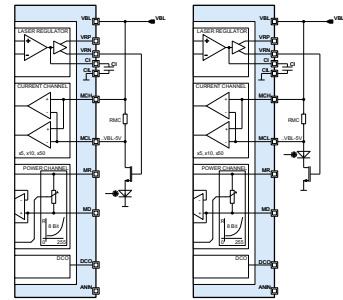


Figure 23: Working in ACC mode with N-channel output transistor.

| EACC | MCVR | EPNPP |
|------|------|-------|
| 1 | 1 | - |

Table 90: Register for Figure 23

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APC mode

Examples of APC mode using N-channel transistor, Figures 24 and 25.

Examples of APC mode using P-channel transistor, Figures 26 and 27.

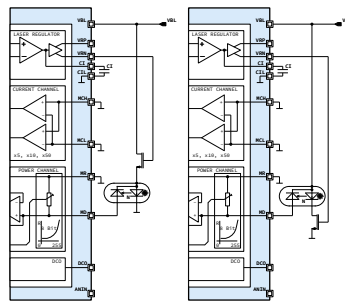


Figure 24: Working with N-channel output transistor and N-type laser diode.

| EACC | MCVR | EPNNP |
|------|------|-------|
| 0 | 0 | 0 |

Table 91: Register for Figure 24

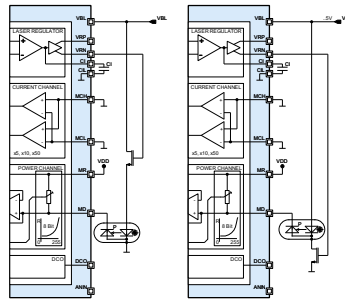


Figure 25: Working with N-channel output transistor and P-type laser diode.

| EACC | MCVR | EPNNP |
|------|------|-------|
| 0 | 0 | 1 |

Table 92: Register for Figure 25

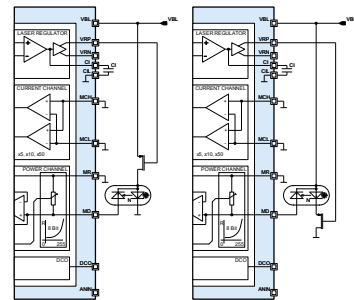


Figure 26: Working with P-channel output transistor and N-type laser diode.

| EACC | MCVR | EPNNP |
|------|------|-------|
| 0 | 0 | 0 |

Table 93: Register for Figure 26

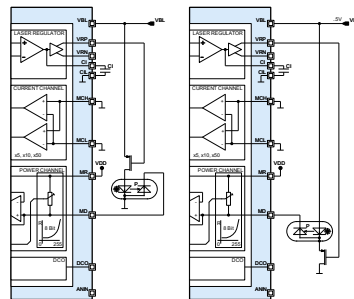


Figure 27: Working with P-channel output transistor and P-type laser diode.

| EACC | MCVR | EPNNP |
|------|------|-------|
| 0 | 0 | 1 |

Table 94: Register for Figure 27

Note that in Figures 25 right and 27 right the VBL voltage is limited to 5 V.

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APC mode with current monitor or ACC mode with optical power monitor

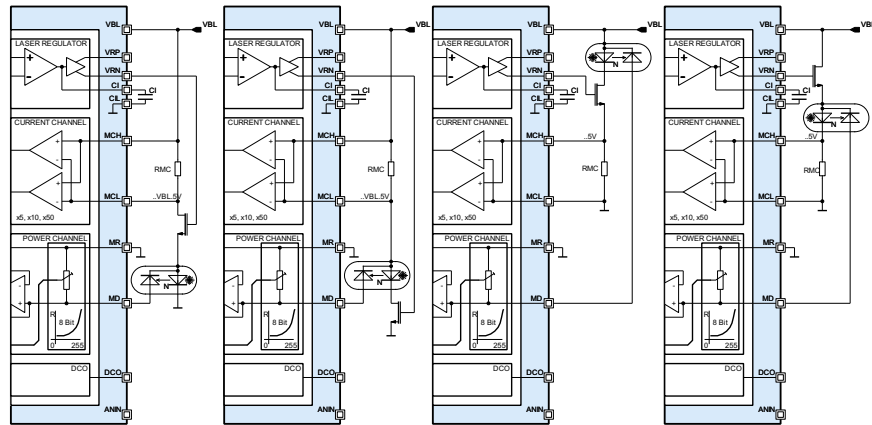


Figure 28: iC-HTG with N-channel output transistor and N-type laser diode.

| Register | Figure 28.a | Figure 28.b | Figure 28.c | Figure 28.d | EACC | ADCC |
|----------|-------------|-------------|-------------|-------------|------|------|
| MCVR | 1 | 1 | 0 | 0 | 1 | 011 |
| EPNNP | 0 | 0 | 0 | 0 | 0 | 100 |

Table 95: Configuration register for Figure 28

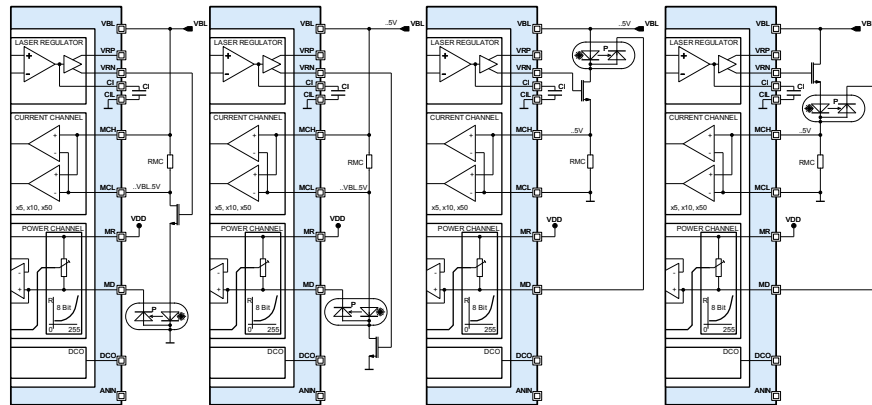


Figure 29: iC-HTG with N-channel output transistor and P-type laser diode

| Register | Figure 29.a | Figure 29.b | Figure 29.c | Figure 29.d | EACC | ADCC |
|----------|-------------|-------------|-------------|-------------|------|------|
| MCVR | 1 | 1 | 0 | 0 | 1 | 011 |
| EPNNP | 1 | 1 | 1 | 1 | 0 | 100 |

Table 96: Configuration register for Figure 29

Note that in Figures 29.b and 29.c the VBL voltage is limited to 5 V.

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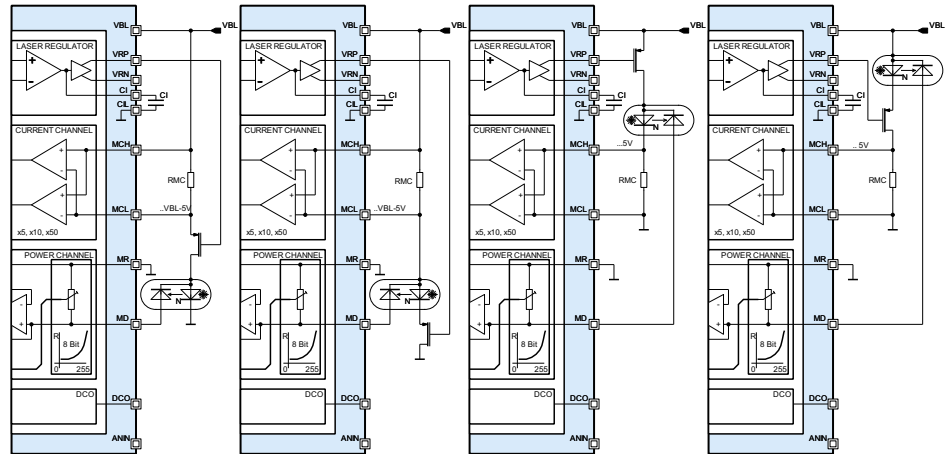


Figure 30: iC-HTG with P-channel output transistor and N-type laser diode.

| Register | Figure 30.a | Figure 30.b | Figure 30.c | Figure 30.d | EACC | ADCC |
|----------|-------------|-------------|-------------|-------------|------|------|
| MCVR | 1 | 1 | 0 | 0 | 1 | 011 |
| EPNNP | 0 | 0 | 0 | 0 | 0 | 100 |

Table 97: Configuration register for Figure 30

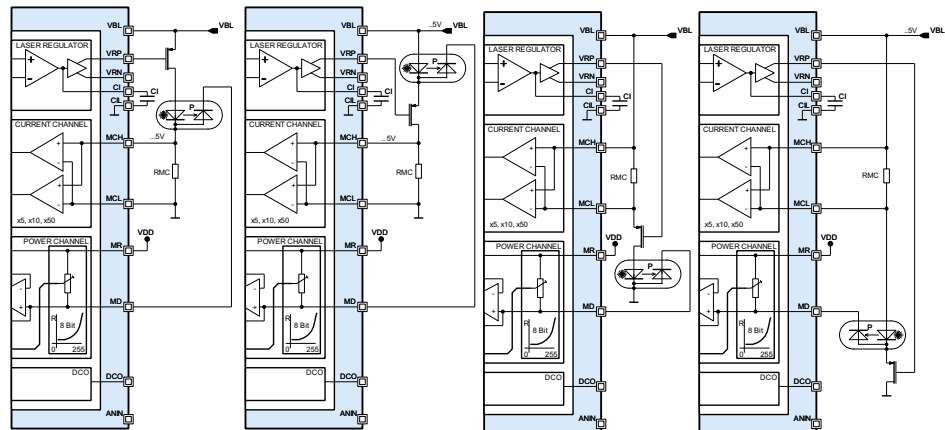


Figure 31: iC-HTG with P-channel output transistor and P-type laser diode

| Register | Figure 31.a | Figure 31.b | Figure 31.c | Figure 31.d | EACC | ADCC |
|----------|-------------|-------------|-------------|-------------|------|------|
| MCVR | 0 | 0 | 1 | 1 | 1 | 011 |
| EPNNP | 1 | 1 | 1 | 1 | 0 | 100 |

Table 98: Configuration register for Figure 31

Note that in Figures 31.b and 31.d the VBL voltage is limited to 5V.

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DESIGN REVIEW: Notes On Chip Functions

| iC-HTG Z, Z1 | | |
|--------------|--------------------------|---|
| No. | Function, Parameter/Code | Description and Application Notes |
| 1 | NEBUF | For iC-HTG chip releases Z and Z1 it is NOT recommended to use NEBUF = 0. Otherwise, proper operation of the control loop can not be guaranteed for all conditions. The parameter NEBUF does not exist anymore with iC-HTG chip release Y or higher. |
| 2 | CHIPREV | For iC-HTG chip releases see Table 62. |

Table 99: Notes on chip functions regarding iC-HTG chip release Z and Z1

| iC-HTG Y, Y1 | | |
|--------------|--------------------------|---|
| No. | Function, Parameter/Code | Description and Application Notes |
| 1 | VRNHR | Voltage output range selection for VRN. More information on Table 86 and page 16. |
| 2 | CHIPREV | For iC-HTG chip releases see Table 62. |

Table 100: Notes on chip functions regarding iC-HTG chip release Y and Y1

| iC-HTG X | | |
|----------|--|--|
| No. | Function, Parameter/Code | Description and Application Notes |
| 1 | DRDY | Data Ready Status Register for A/D Synchronisation. More information on page 21. |
| 2 | ENADCDIV | Save current bit if voltage dividers are not used in AD. More information on page 21 |
| 3 | LINLOG | Logarithmic DA converter can be set as linear one. More information on page 21 |
| 4 | ESD | Internal ESD Protection under 500 V |
| 5 | CHIPREV | For iC-HTG chip releases see Table 62. |
| 6 | Permissible Supply Voltage at VB, Electrical Characteristics No. 001 | VB = 10 V max. |

Table 101: Notes on chip functions regarding iC-HTG chip release X

| iC-HTG W1 | | |
|-----------|--------------------------|--|
| No. | Function, Parameter/Code | Description and Application Notes |
| 1 | CHIPREV | For iC-HTG chip releases see Table 62. |

Table 102: Notes on chip functions regarding iC-HTG chip release W1

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REVISION HISTORY

| Rel. | Rel. Date [†] | Chapter | Modification | Page |
|------|------------------------|---------|-----------------|------|
| A1 | 2017-11-24 | | Initial release | |

| Rel. | Rel. Date [†] | Chapter | Modification | Page |
|------|------------------------|---|--|------|
| B1 | 2020-10-01 | DESCRIPTION | Poti max. value changed form 500 to 407 kΩ | 2 |
| | | ABSOLUTE MAXIMUM RATINGS | G005, G007: pin EC added | 6 |
| | | ELECTRICAL CHARACTERISTICS | Operating Conditions: VB = VBL = 3 ... 24 V (relative to GND), Tj = -40 ... 125 °C unless otherwise stated | 7-10 |
| | | ELECTRICAL CHARACTERISTICS | Specification Updated at Item No. 003, 006, 008, 012, 103, 303, 502 added and inserted, 304 ... 306, 107 ... 110, 402, 605, 609, 711, C03, D02 and E02 | 7-10 |
| | | STANDBY | Additional series resistor when connecting NSTY to VB | 12 |
| | | OPERATION MODE | Renamed PDVDD => PDOVDD | 13 |
| | | CONTROL MODES AND LASER DIODE/LED TYPES | New function Register VRNHR described | 16 |
| | | 8-BIT INTERNAL PROGRAMMABLE LOGARITHMIC MONITOR RESISTORS | Poti max. value changed form 500 to 407 kΩ | 20 |
| | | 10-BIT LOGARITHMIC D/A CONVERTER | New Linear Reference Mode described (introduced in HTG_X version) | 20 |
| | | 10-BIT LINEAR A/D CONVERTER | New register DRDY and ANADCDIV described. New method for synchronisation of the AD described. (introduced in HTG_X version) | 21 |
| | | 10-BIT LINEAR A/D CONVERTER | Readout advise added | 22 |
| | | REGISTER OVERVIEW | Updated | 29 |
| | | DESIGN REVIEW: Notes On Chip Functions | Chapters added | 41 |

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[†] Release Date format: YYYY-MM-DD

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ORDERING INFORMATION

| Type | Package | Order Designation |
|------------------|---------------------------|-------------------|
| iC-HTG | QFN24 4 mm x 4 mm | iC-HTG QFN24-4x4 |
| Evaluation Board | 100 mm x 80 mm eval board | iC-HTG EVAL HTG1D |

Please send your purchase orders to our order handling team.

For technical support, information about prices and terms of delivery please contact us.